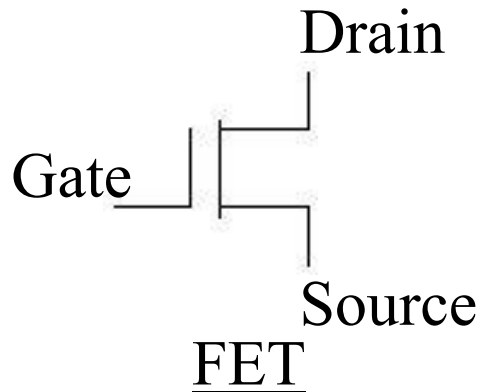


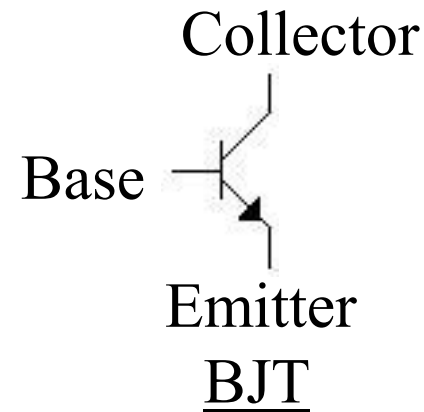
FIELD EFFECT TRANSISTORS (FET)

Dr. Vivek Ambalkar

FET x BJT (NPN)



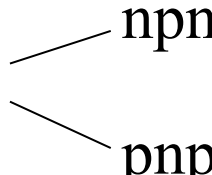
- ✓ 3 terminal device
- ✓ Channel e^- current from source to drain controlled by the electric field generated by the gate
- ✓ Extremely high input impedance for base

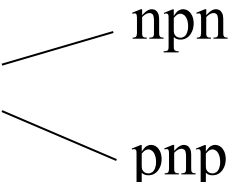


- ✓ 3 terminal device emitter to collector e^- current controlled by the current injected into the base

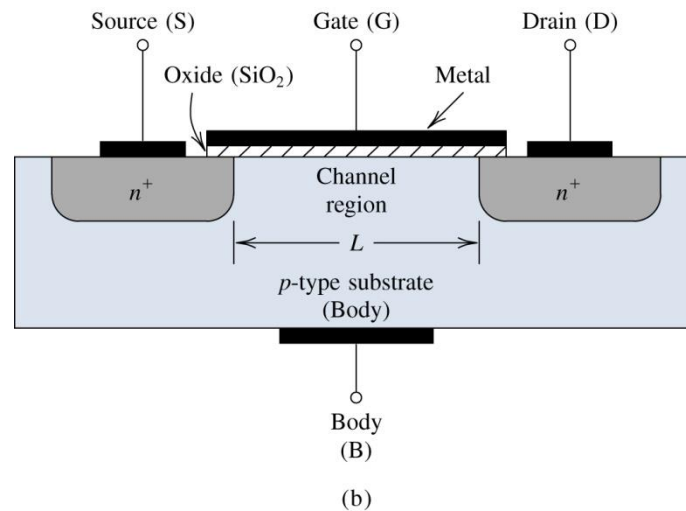
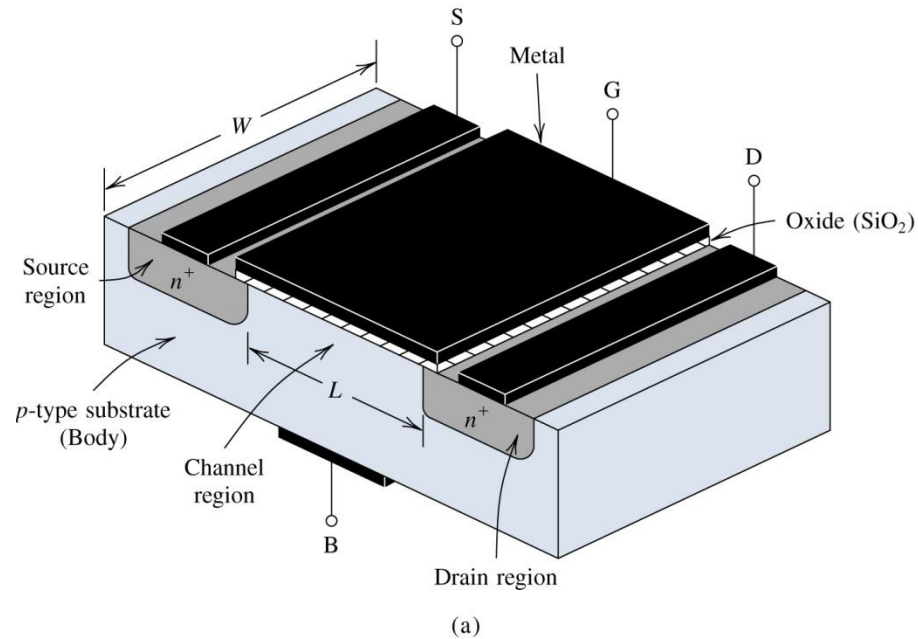
Types of FETs

- In addition to carrier type (N or P channel), there are differences in how the control element is constructed (Junction x Insulated) and those devices must be used differently

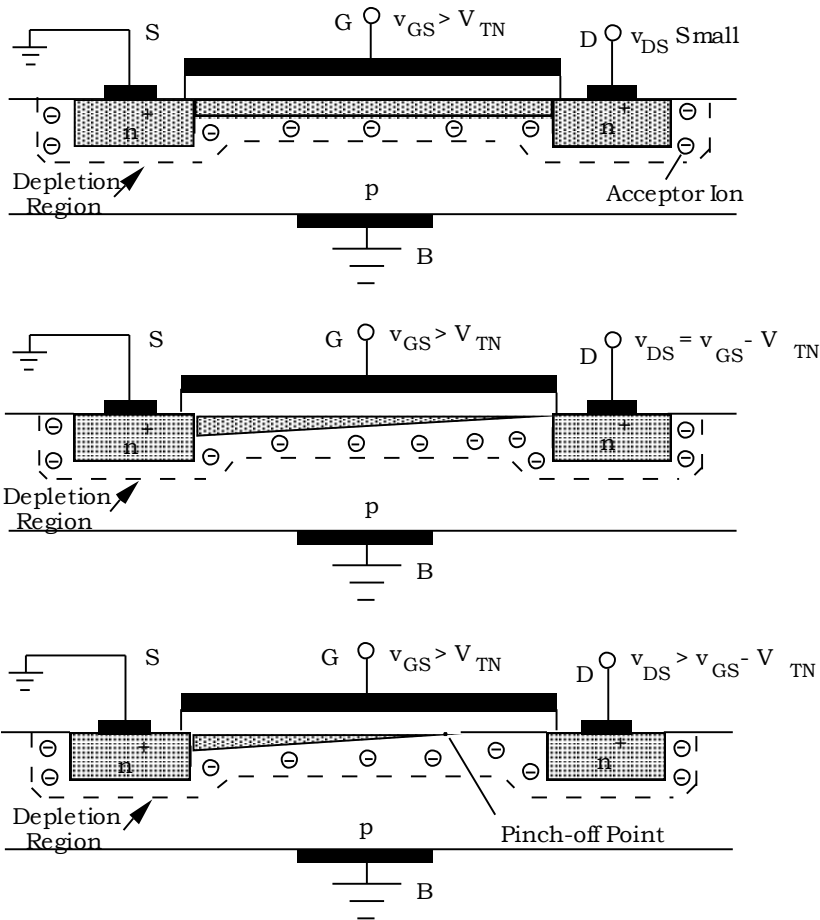
Depletion mode junction FETs (JFET) 

Metal oxide semi-conductor FET (MOSFET) 
– depletion/enhancement mode
– enhancement mode

(insulated gate FETs, IGFETs, are the same as MOSFETs)

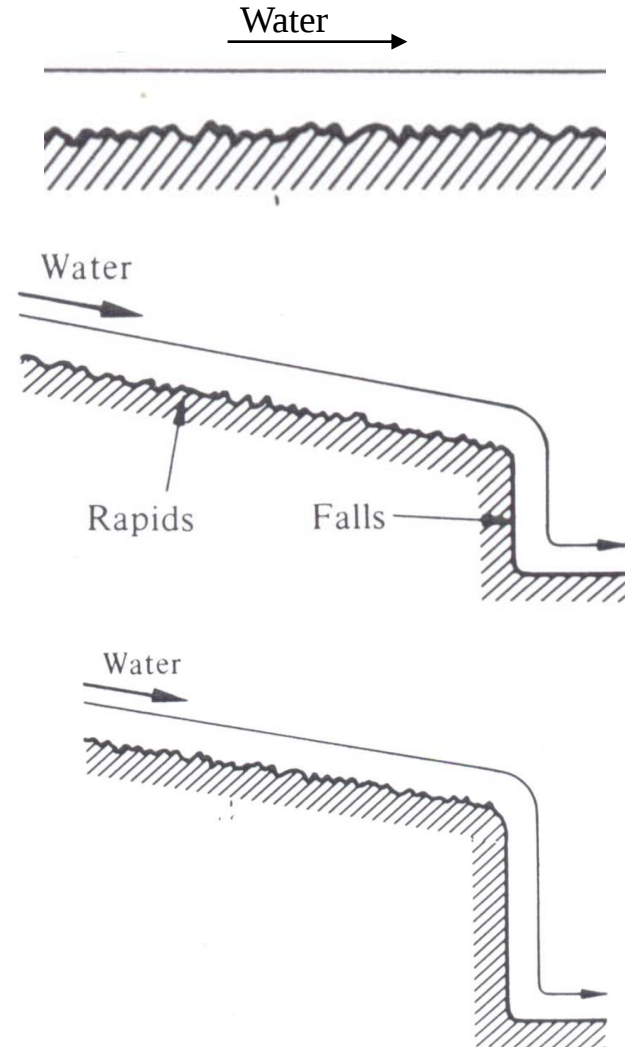


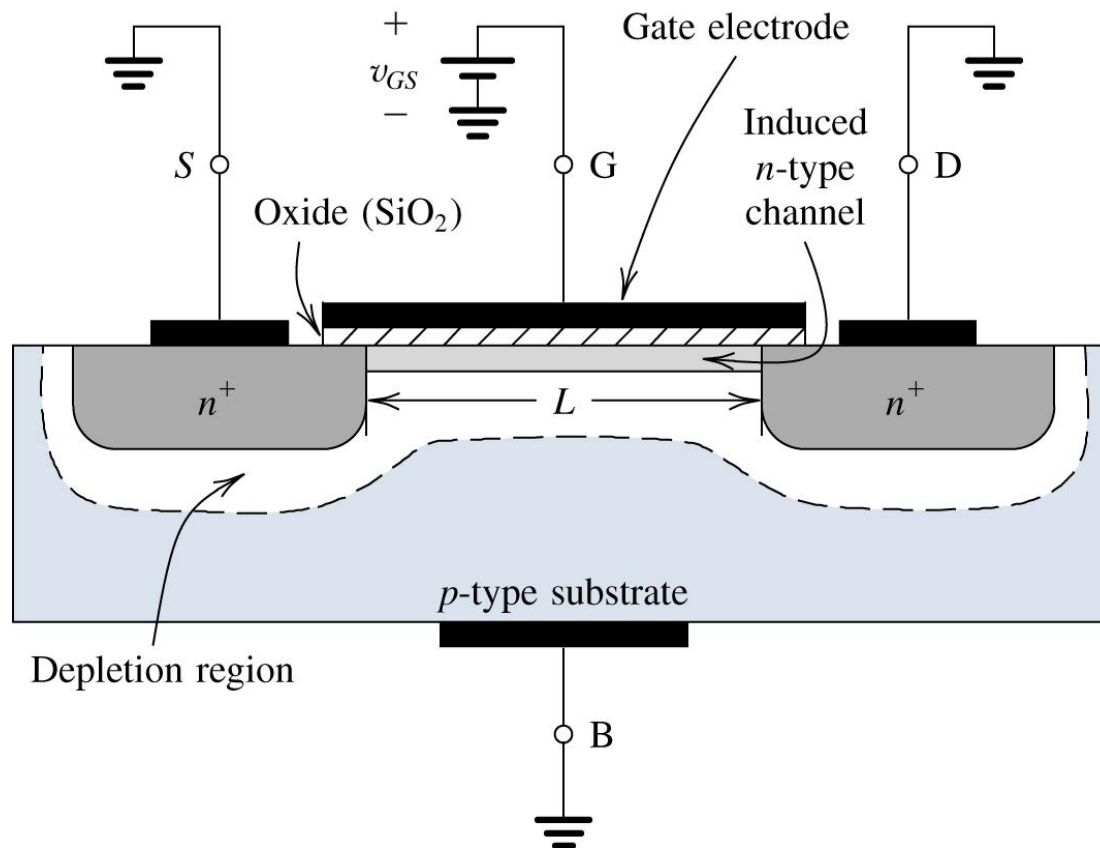
Physical structure of the enhancement-type NMOS transistor: **(a)** perspective view; **(b)** cross section. Typically $L = 1$ to $10\ \mu\text{m}$, $W = 2$ to $500\ \mu\text{m}$, and the thickness of the oxide layer is in the range of 0.02 to $0.1\ \mu\text{m}$.



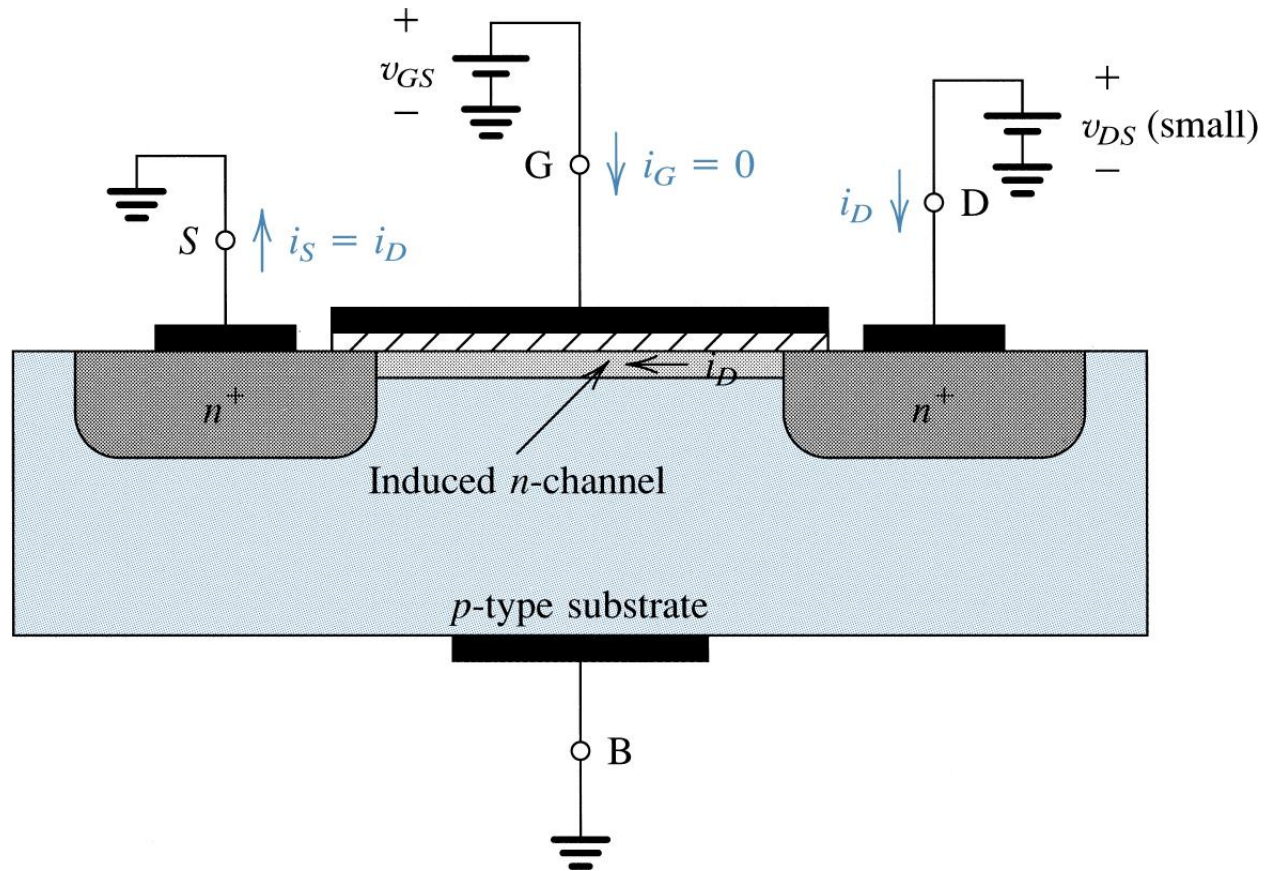
- (a) MOSFET in the linear region
- (b) MOSFET with channel just pinched off at the drain.
- (c) Channel pinch off for $v_{DS} > v_{GS} - V_{TN}$

Waterfalls analogy





The enhancement-type NMOS transistor with a positive voltage applied to the gate. An n channel is induced at the top of the substrate beneath the gate.

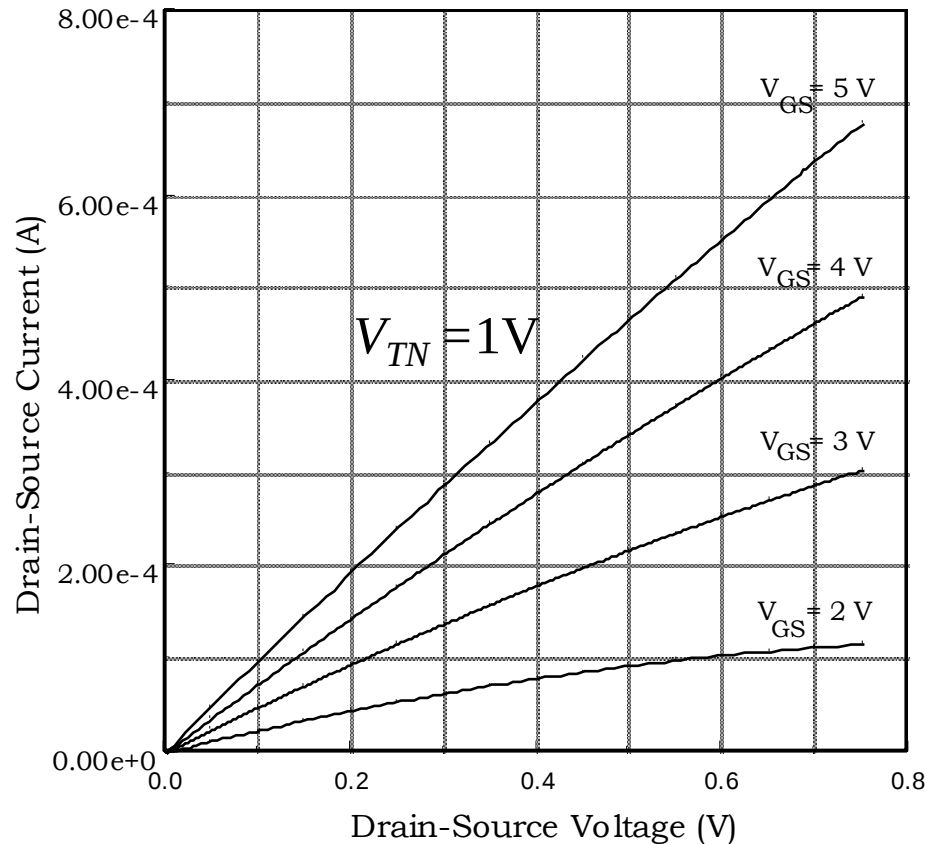


An NMOS transistor with $v_{GS} > V_t$ and with a small v_{DS} applied. The device acts as a conductance whose value is determined by v_{GS} . Specifically, the channel conductance is proportional to $v_{GS} - V_t$, and this i_D is proportional to $(v_{GS} - V_t) v_{DS}$. Note that the depletion region is not shown (for simplicity).

$$i_D = \mu_n C_{OX} \frac{W}{L} \left[(v_{GS} - V_{tn}) v_{DS} - \frac{v_{DS}^2}{2} \right]$$

$$v_{GS} \geq V_{tn}$$

$$0 \leq v_{DS} \leq v_{DSSAT} = v_{GS} - V_{tn}$$



NMOS i-v characteristics in the linear region ($V_{SB} = 0$)

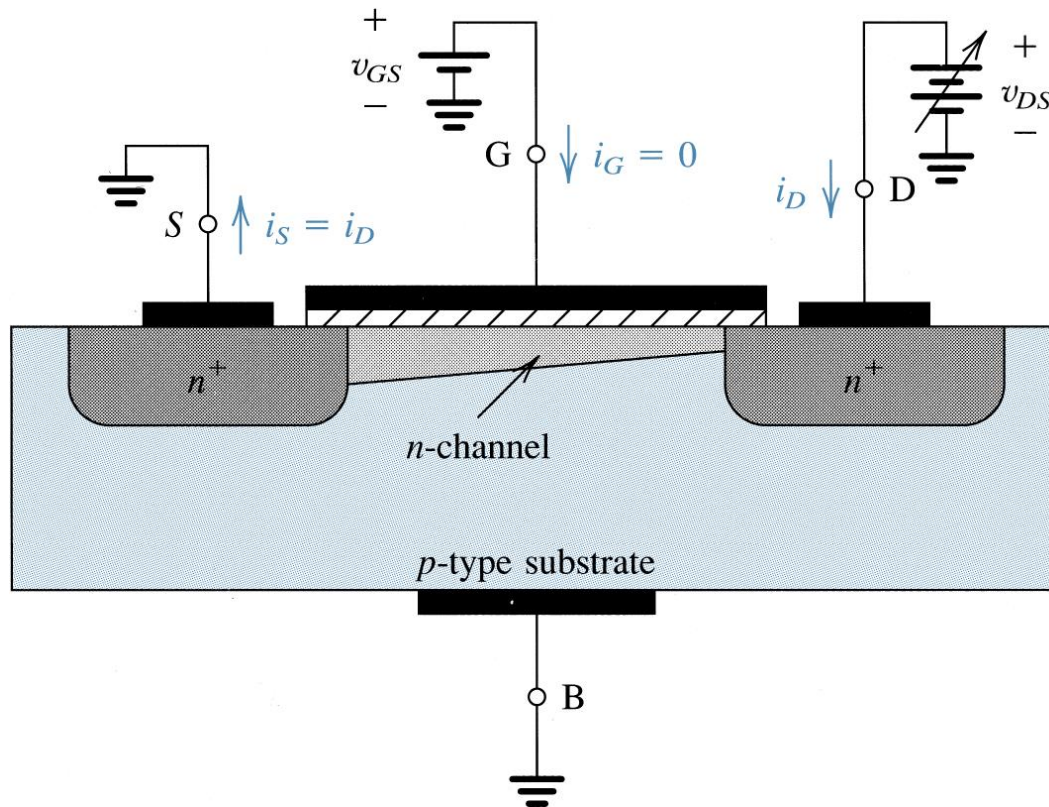
$$k'_n = \mu_n C_{OX}$$

small v_{DS}

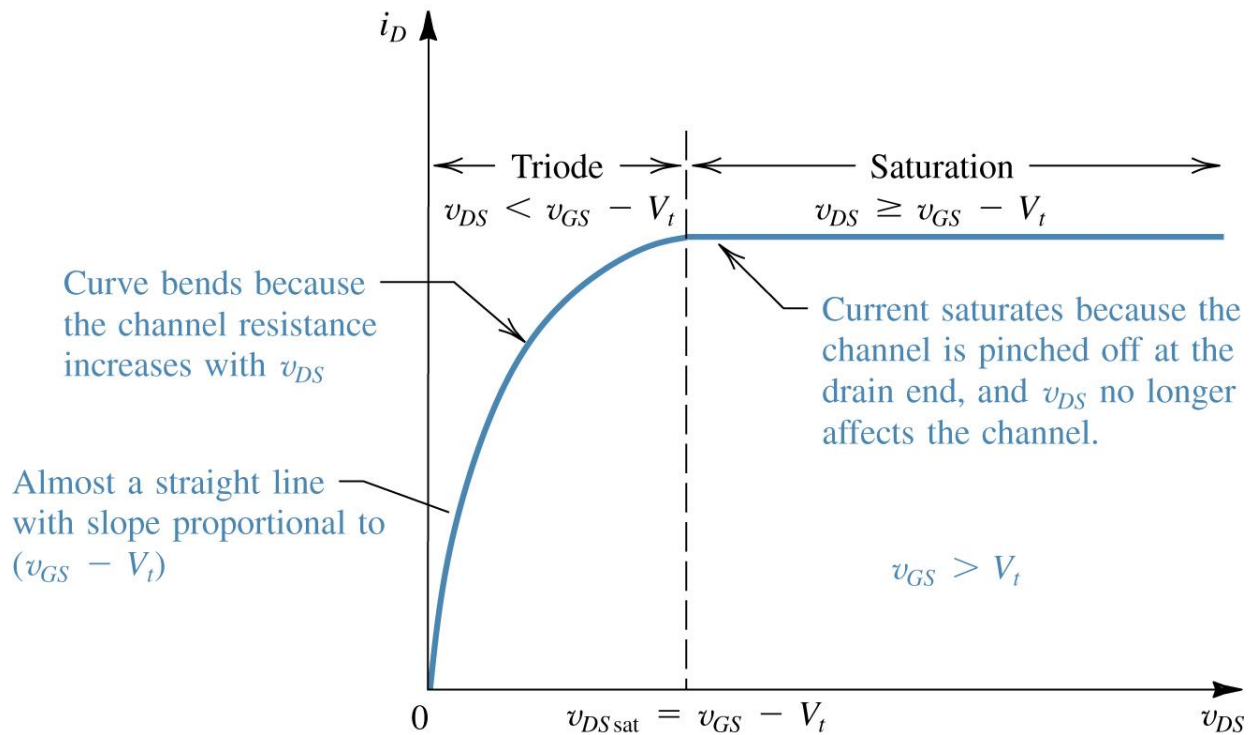
$$i_D = k'_n \frac{W}{L} (v_{GS} - V_{tn}) v_{DS}$$

$$\frac{di_D}{dv_{DS}} = k'_n \frac{W}{L} (v_{GS} - V_{tn})$$

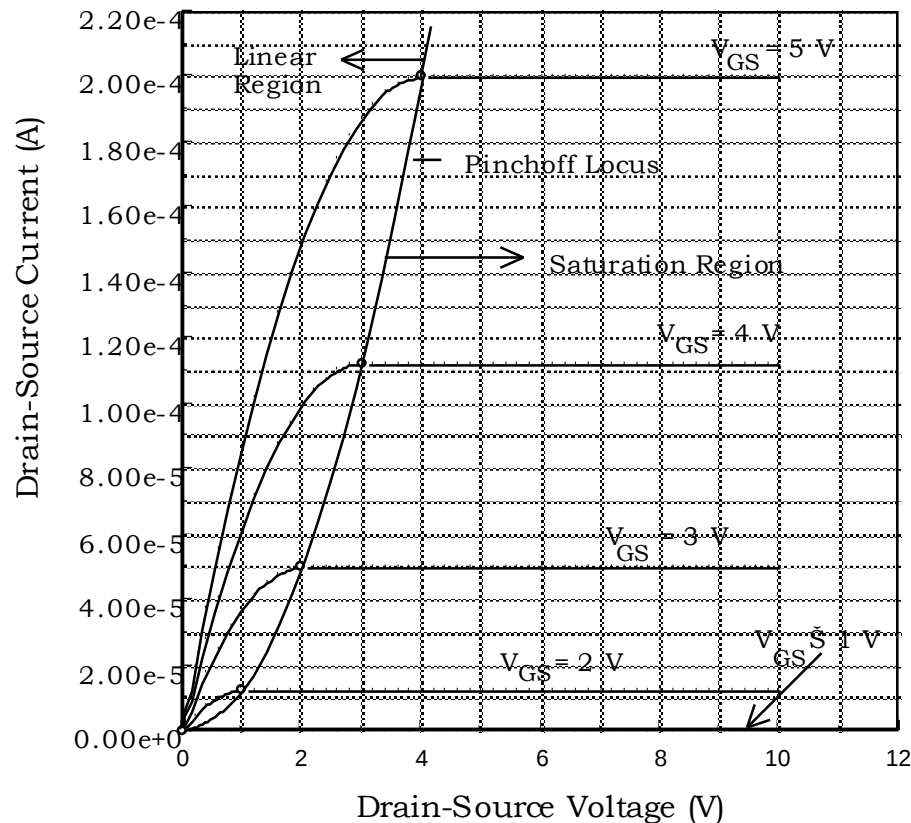
Linear Region (*small* v_{DS})



Operation of the enhancement NMOS transistor as v_{DS} is increased. The induced channel acquires a tapered shape and its resistance increases as v_{DS} is increased. Here, v_{GS} is kept constant at a value $> V_t$.



The drain current i_D versus the drain-to-source voltage v_{DS} for an enhancement-type NMOS transistor operated with $v_{GS} > V_t$.



Output characteristics
for an NMOS transistor with
 $V_{tn} = 1 \text{ V}$ and $k'_n (W/L) = 25 \times 10^{-6} \text{ A/V}^2$

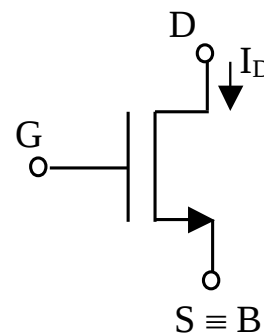
$$i_D \approx 0 \quad \text{for} \quad v_{GS} \leq V_{tn}$$

$$i_D = k'_n \frac{W}{L} \left[(v_{GS} - V_{tn})v_{DS} - \frac{v_{DS}^2}{2} \right]$$

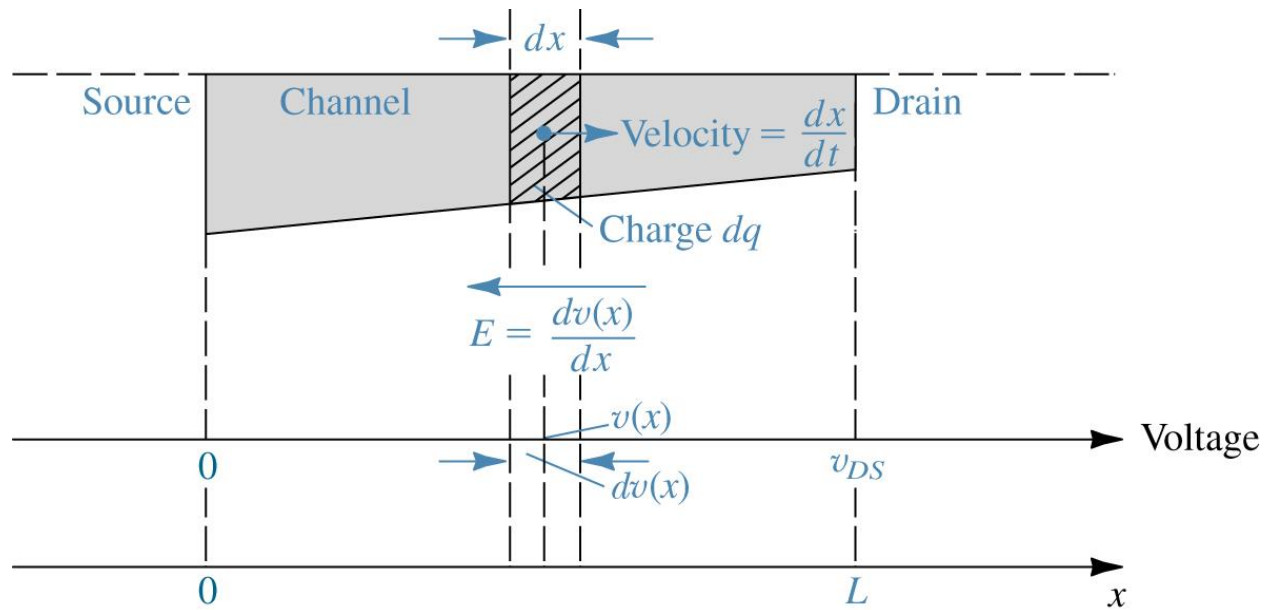
$$\text{for} \quad \begin{cases} v_{GS} \geq V_{tn} \\ v_{DS} \leq v_{DS_{SAT}} = v_{GS} - V_{tn} \end{cases}$$

$$i_D = \frac{k'_n}{2} \frac{W}{L} (v_{GS} - V_{tn})^2$$

$$\text{for} \quad \begin{cases} v_{GS} \geq V_{tn} \\ v_{DS} \geq v_{DS_{SAT}} = v_{GS} - V_{tn} \end{cases}$$

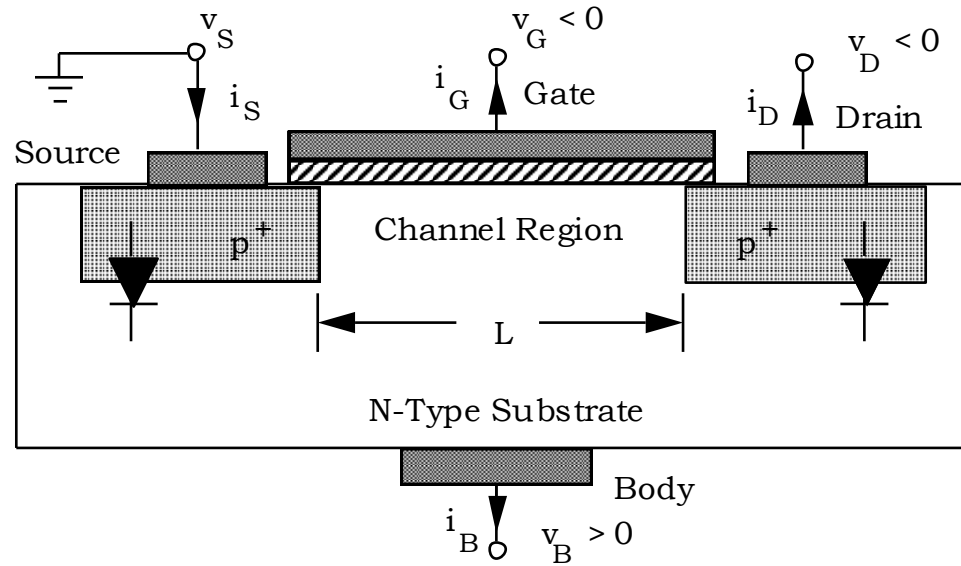


$$v_D \geq v_S$$

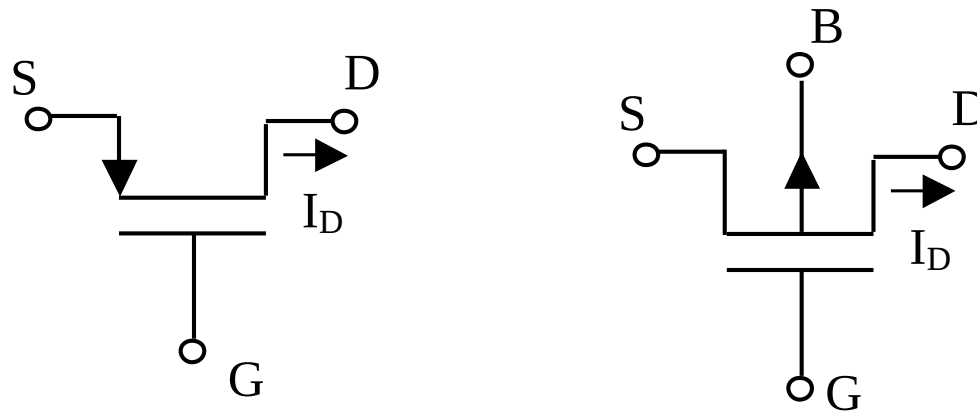


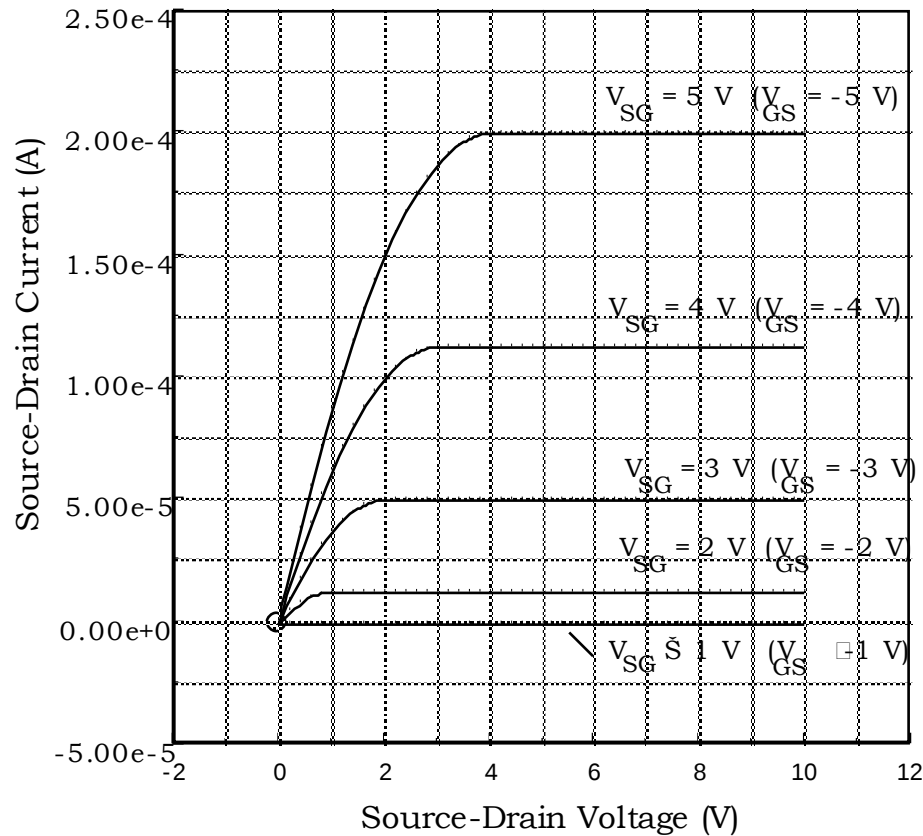
Derivation of the $i_D - v_{DS}$ characteristic of the NMOS transistor.

The PMOS Transistor



Cross section of an enhancement-mode PMOS transistor





Output characteristics for a PMOS transistor with $V_{tp} = -1\text{V}$ and $k'_p (W/L) = 25 \times 10^{-6} \text{ A/V}^2$

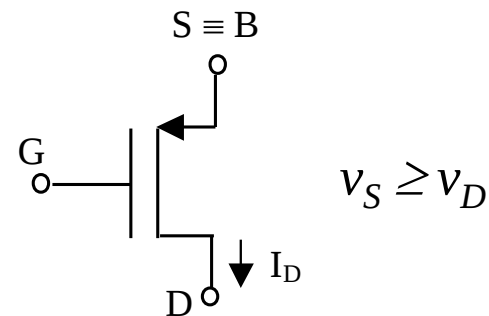
$$i_D \approx 0 \quad \text{for} \quad v_{GS} \geq V_{tp}$$

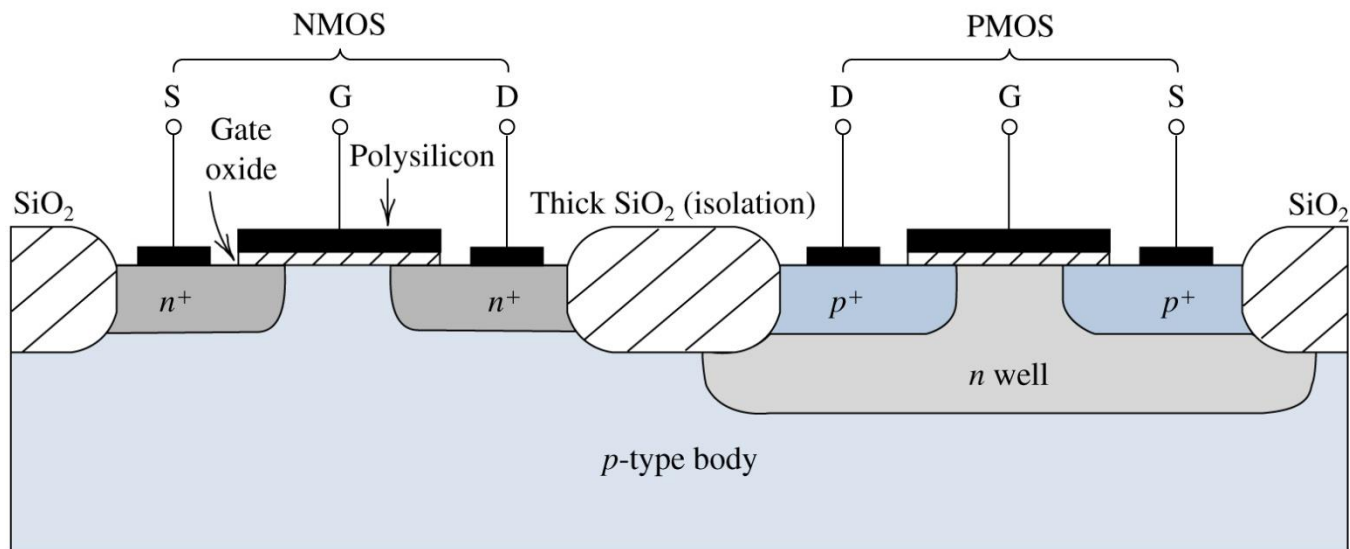
$$i_D = k'_p \frac{W}{L} \left[(v_{GS} - V_{tp}) v_{DS} - \frac{v_{DS}^2}{2} \right]$$

$$\text{for} \begin{cases} v_{GS} \leq V_{tp} \\ v_{DS} \geq v_{DS_{SAT}} = v_{GS} - V_{tp} \end{cases}$$

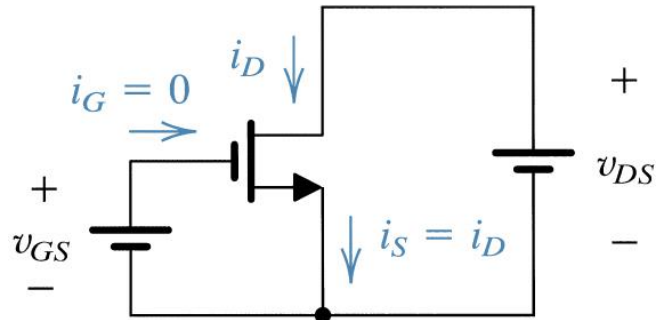
$$i_D = \frac{k'_p}{2} \frac{W}{L} (v_{GS} - V_{tp})^2$$

$$\text{for} \begin{cases} v_{GS} \leq V_{tp} \\ v_{DS} \leq v_{DS_{SAT}} = v_{GS} - V_{tp} \end{cases}$$

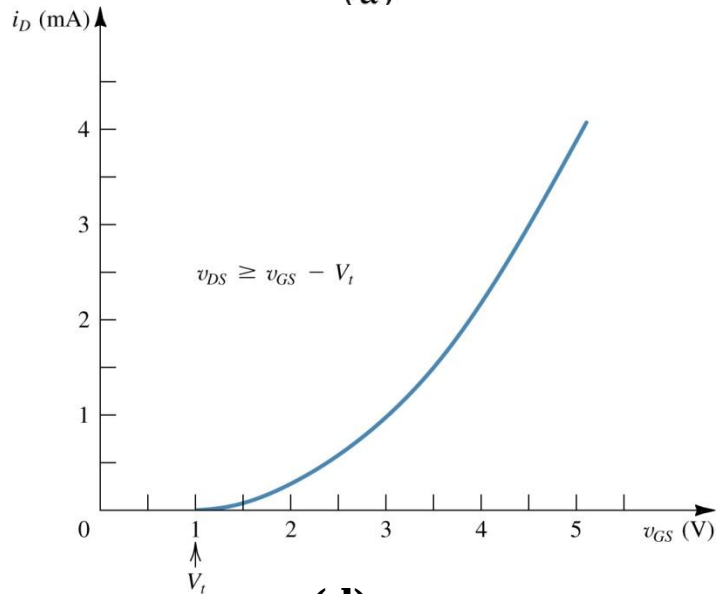




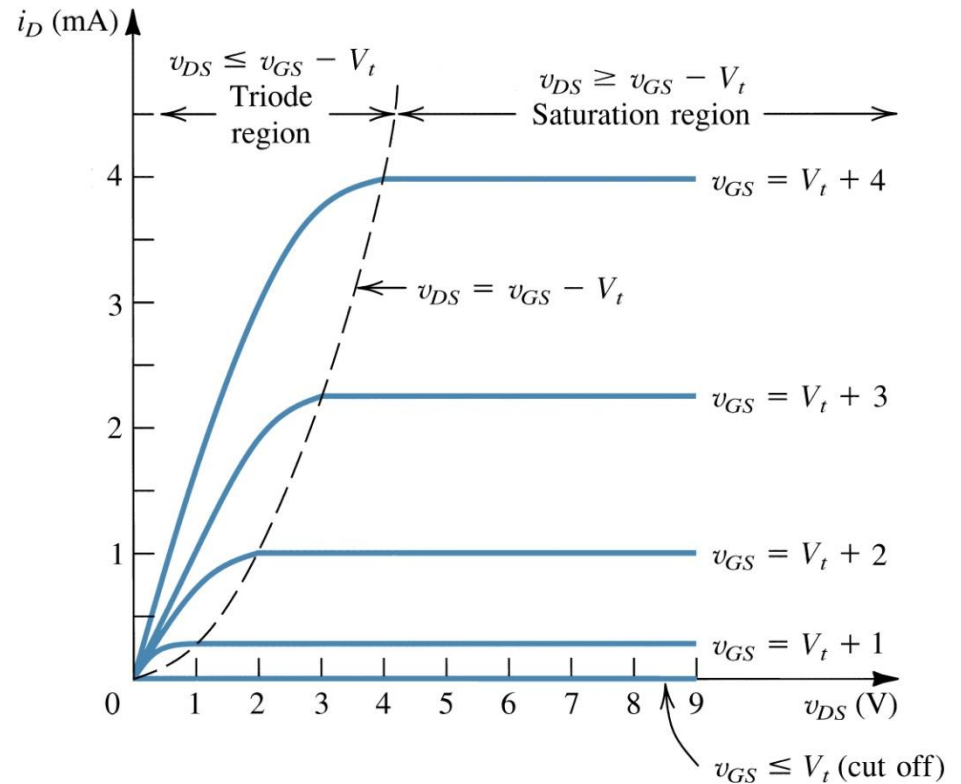
Cross section of a CMOS integrated circuit. Note that the PMOS transistor is formed in a separate *n*-type region, known as an *n* well. Another arrangement is also possible in which an *n*-type body is used and the *n* device is formed in a *p* well.



(a)



(d)



- (a) An n-channel enhancement-type MOSFET with v_{GS} and v_{DS} applied and with the normal directions of current flow indicated.
 (b) The $i_D - v_{DS}$ characteristics for a device with $V_t = 1$ V and $k'_n(W/L) = 0.5$ mA/V² (d) The $i_D - v_{GS}$ characteristic for an enhancement-type NMOS transistor in saturation.

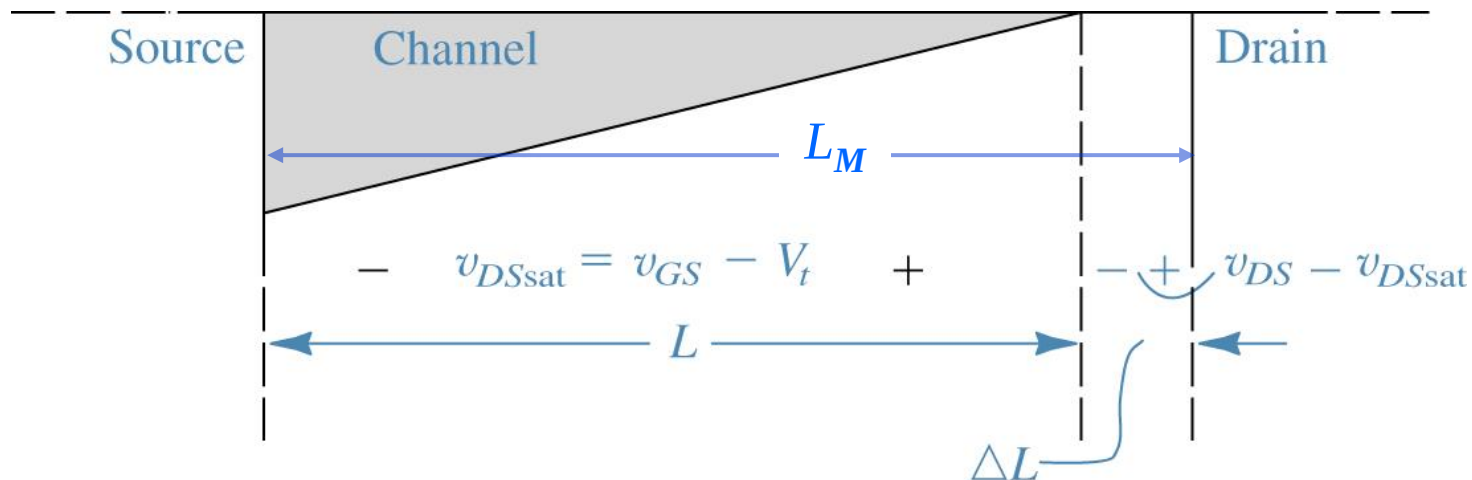
Channel Length Modulation

$$i_D = \frac{\mu C_{ox}}{2} \frac{W}{L} (v_{GS} - V_t)^2 = I_{D_{SAT}} \rightarrow L = L_M$$

$$i_D = \frac{I_{D_{SAT}}}{1 - \Delta L / L_M} \cong I_{D_{SAT}} \left(1 + \Delta L / L_M \right)$$

$$\Delta L / L_M = \lambda v_{DS} \quad \therefore \frac{1}{\lambda} = V_A \propto L$$

$$i_D = \frac{\mu C_{ox}}{2} \frac{W}{L} (v_{GS} - V_t)^2 (1 + \lambda v_{DS})$$



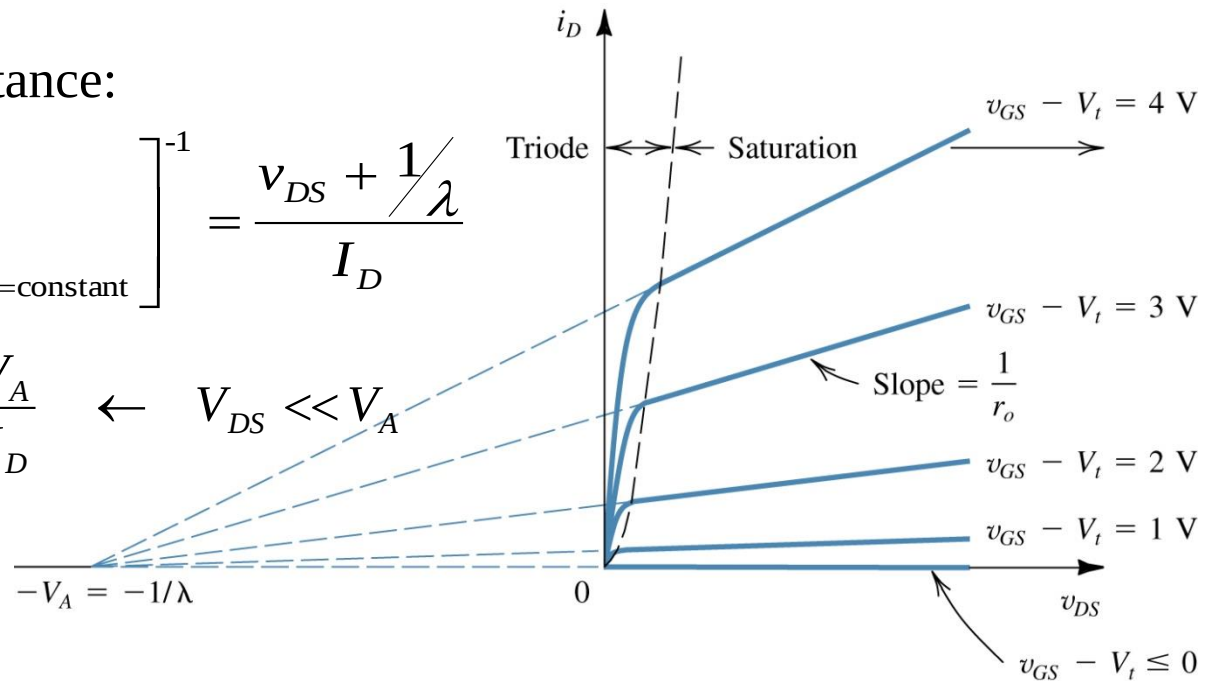
Increasing v_{DS} beyond v_{DSsat} causes the channel pinch-off point to move slightly away from the drain, thus reducing the effective channel length (by ΔL).

$$i_D = \frac{\mu C_{ox}}{2} \frac{W}{L} (v_{GS} - V_t)^2 (1 + \lambda v_{DS}) \leftarrow \text{Saturation}$$

Output Resistance:

$$r_o = \left[\left. \frac{\partial i_D}{\partial v_{DS}} \right|_{v_{GS}=\text{constant}} \right]^{-1} = \frac{v_{DS} + 1/\lambda}{I_D}$$

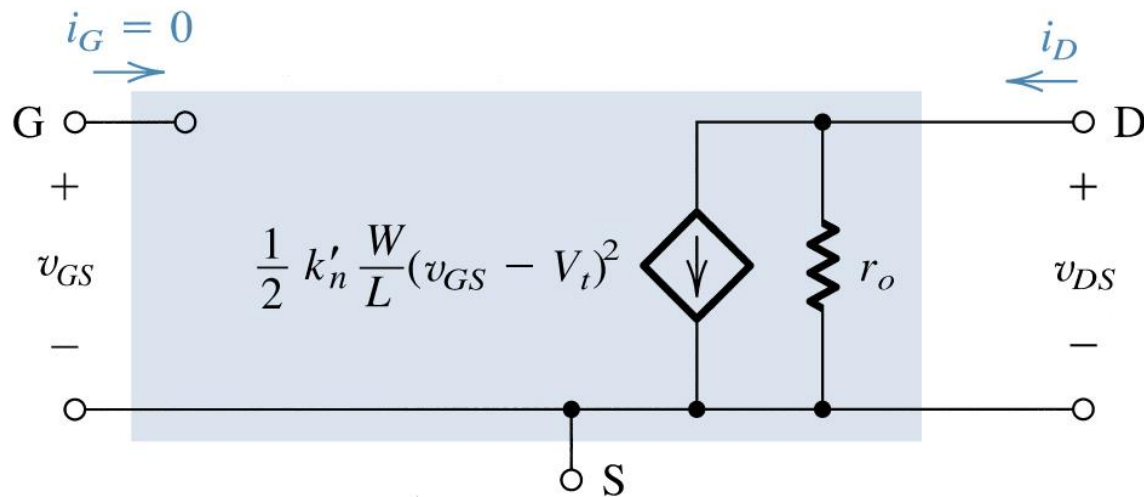
$$r_o \approx [\lambda I_D]^{-1} = \frac{V_A}{I_D} \leftarrow V_{DS} \ll V_A$$



V_A is directly proportional to L ; thus two devices with the same process, and having channel lengths L_1 e L_2 , will have Early voltage V_{A1} and V_{A2} .

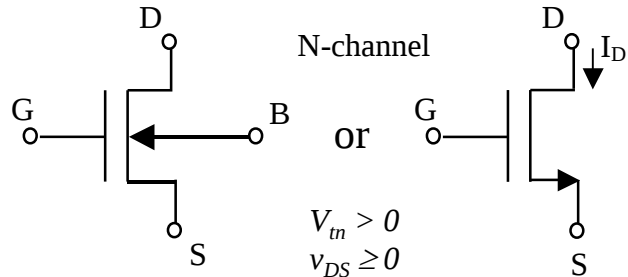
$$\frac{V_{A1}}{V_{A2}} \cong \frac{L_1}{L_2}$$

Effect of v_{DS} on i_D in the saturation region. The MOSFET parameter V_A is typically in the range of 30 to 200 V.



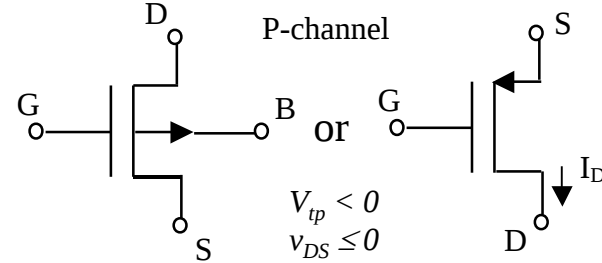
Large-signal equivalent circuit model of the n -channel MOSFET in saturation, incorporating the output resistance r_o . The output resistance models the linear dependence of i_D on v_{DS} and is given by $r_o \cong V_A/I_D$.

Summary of equations for the enhancement-mode MOSFET

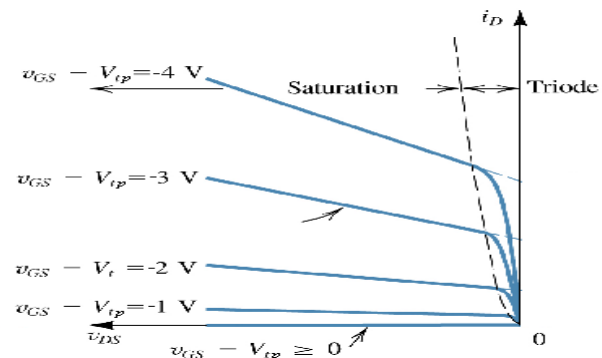
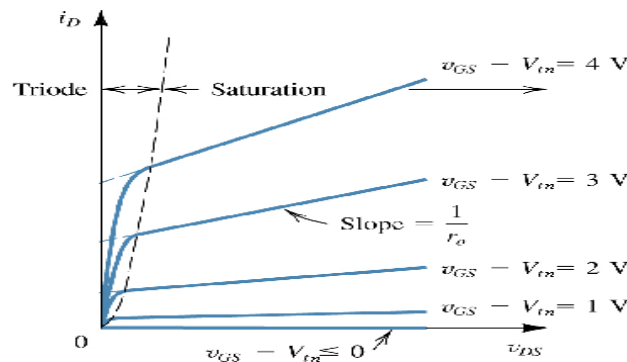


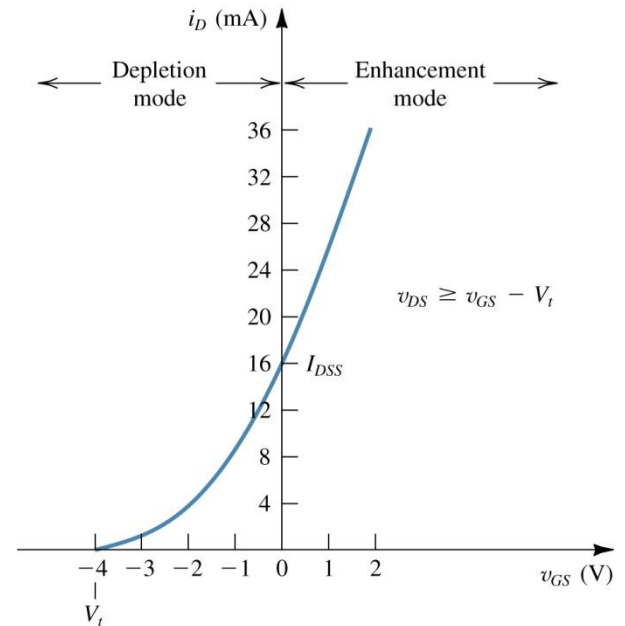
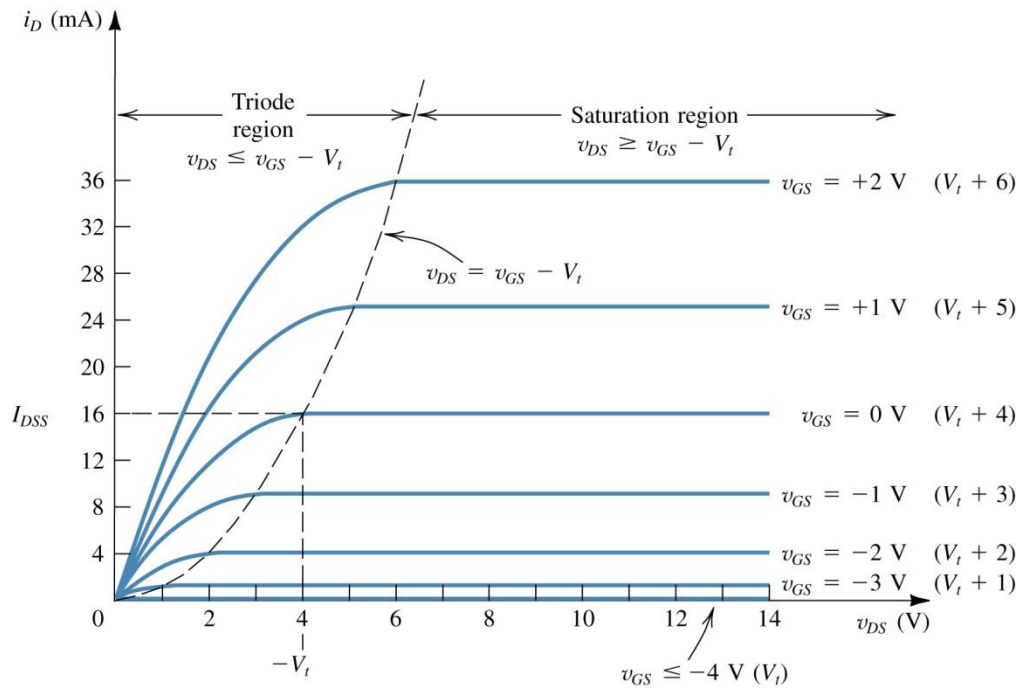
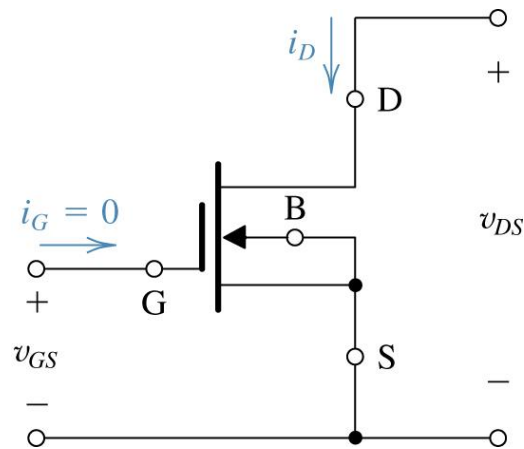
$$k'_n = \mu_n C_{ox}$$

$$k'_p = \mu_p C_{ox}$$



Region	N - Type	P - Type
Cutoff	$v_{GS} \leq V_{tn}$ $i_D \approx 0$	$v_{SG} \leq V_{tp} $ $i_D \approx 0$
Triode (Linear)	$v_{GS} \geq V_{tn}$ and $v_{DS} \leq v_{GS} - V_{tn}$ $i_D = k'_n \frac{W}{L} \left[(v_{GS} - V_{tn}) v_{DS} - \frac{v_{DS}^2}{2} \right]$	$v_{SG} \geq V_{tp} $ and $v_{SD} \leq v_{SG} - V_{tp} $ $i_D = k'_p \frac{W}{L} \left[(v_{SG} - V_{tp}) v_{SD} - \frac{v_{SD}^2}{2} \right]$
Saturation	$v_{GS} \geq V_{tn}$ and $v_{DS} \geq v_{GS} - V_{tn}$ $i_D = \frac{k'_n}{2} \frac{W}{L} (v_{GS} - V_{tn})^2 \left(1 + \frac{V_{DS}}{ V_A } \right)$	$v_{SG} \geq V_{tp} $ and $v_{SD} \geq v_{SG} - V_{tp} $ $i_D = \frac{k'_p}{2} \frac{W}{L} (v_{SG} - V_{tp})^2 \left(1 + \frac{V_{SD}}{ V_A } \right)$



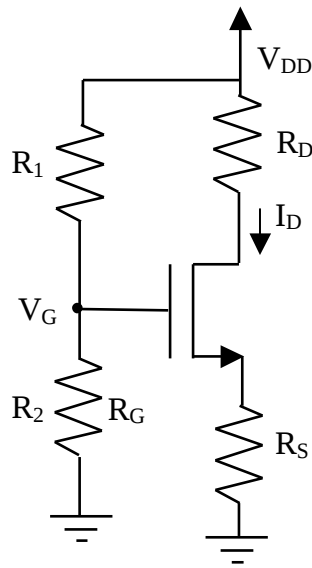


The current-voltage characteristics of a depletion-type n -channel MOSFET for which $V_t = -4$ V and $k'_n(W/L) = 2$ mA/V²:

(a) transistor with current and voltage polarities indicated; (b) the $i_D - v_{DS}$ characteristics; (c) the $i_D - v_{GS}$ characteristic in saturation.

Bias Circuits 1

- λ usually neglected ($1/\lambda = V_A \rightarrow \infty$)
- Q-point most often located in saturation for analog circuits



$$\left. \begin{aligned} V_G &= \frac{R_2}{R_1 + R_2} V_{DD} \\ V_S &= R_S I_D \end{aligned} \right\} \quad V_{GS} = \frac{R_2}{R_1 + R_2} V_{DD} - R_S I_D$$

$$V_{DS} = V_{DD} - (R_D + R_S) I_D$$

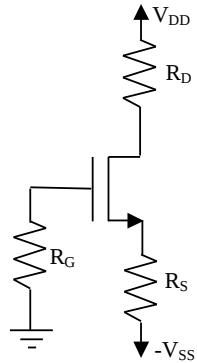
$$I_D = \frac{k'_n}{2} \frac{W}{L} (V_{GS} - V_t)^2 \quad (\text{assuming the MOSFET to be in the saturation region})$$

$$I_D = \frac{k'_n}{2} \frac{W}{L} \left[\frac{R_2}{R_1 + R_2} V_{DD} - V_t - R_S I_D \right]^2 \quad (\text{two solutions} \rightarrow \text{only one is possible})$$

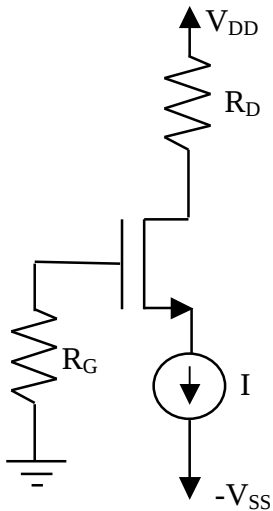
Ex: $V_{DD} = 10 \text{ V}$	$R_1 = 150 \text{ k}\Omega$	$R_2 = 100 \text{ k}\Omega$	$R_S = 10 \text{ k}\Omega$
$R_D = 50 \text{ k}\Omega$	$k'_n(W/L) = 50 \text{ }\mu\text{A/V}^2$	$V_t = 1 \text{ V}$	

Solution: $I_D = 100 \text{ }\mu\text{A}$ $V_{DS} = 4 \text{ V}$

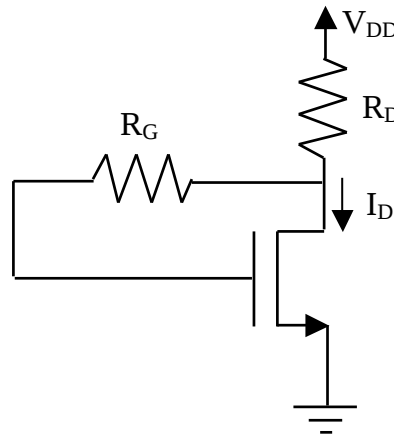
Bias Circuits 2



Two power supplies are available



A simple circuit utilizing a current source



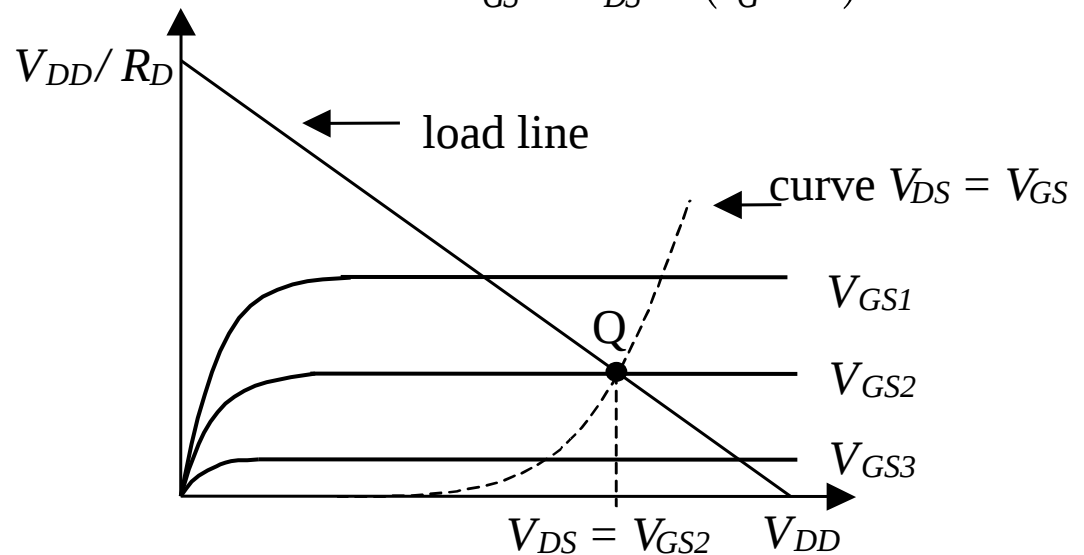
Analysis

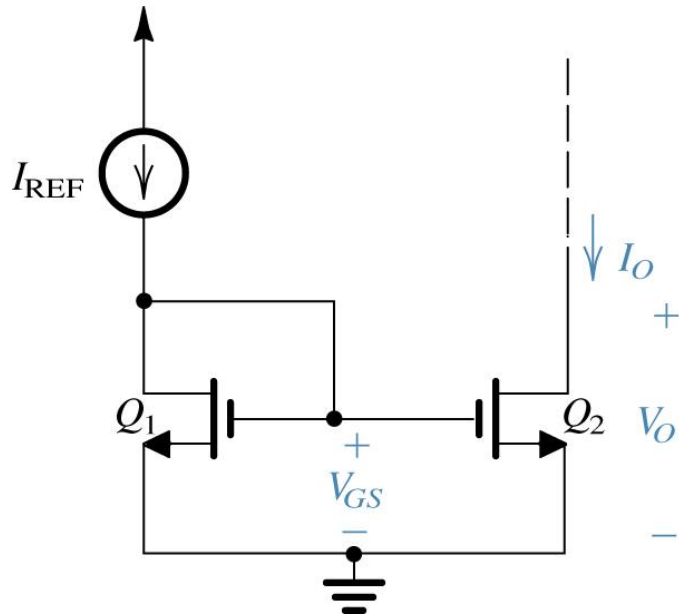
$$I_D = \frac{k'_n}{2} \frac{W}{L} (V_{GS} - V_t)^2$$

$$V_{GS} = V_{DD} - R_D I_D$$

$$I_D = \frac{k'_n}{2} (V_{DD} - V_t - R_D I_D)^2$$

$$V_{GS} = V_{DS} \therefore (I_G = 0)$$





Q_1 : $I \rightarrow V$ converter

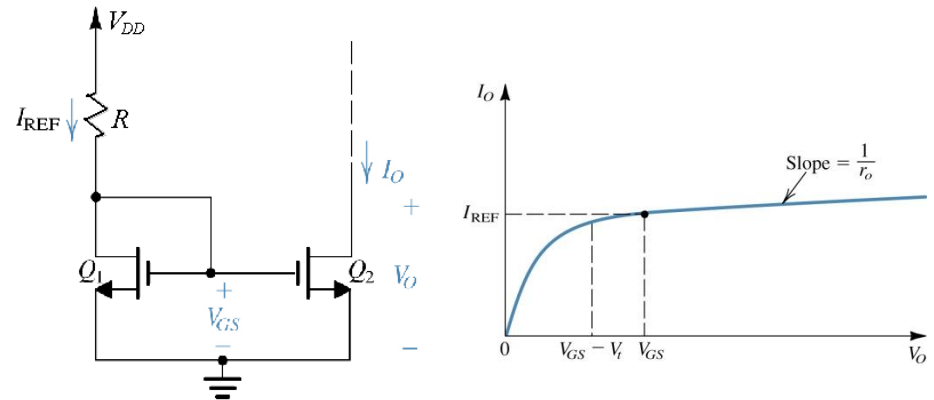
Q_2 : $V \rightarrow I$ converter

If Q_2 in saturation

$$(v_{o_{\min}} = V_{GS} - V_t)$$

then

$$\frac{I_o}{I_{REF}} = \frac{(W/L)_2}{(W/L)_1}$$



Example: $V_{DD} = 5V$; $I_{REF} = 10\mu A$; Q_1 and Q_2 are matched; $L = 10\mu m$ and $W = 100\mu m$; $V_t = 1V$; $k'_n = 20\mu A/V^2$ $V_A = 10L$; $\Delta V_o = +3V$

$$I_{D1} = I_{REF} = 100 = \frac{1}{2} 20 \frac{100}{10} (V_{GS} - 1)^2$$

$$V_{GS} = 2V$$

$$R = \frac{5 - 2}{100\mu} = 30K\Omega$$

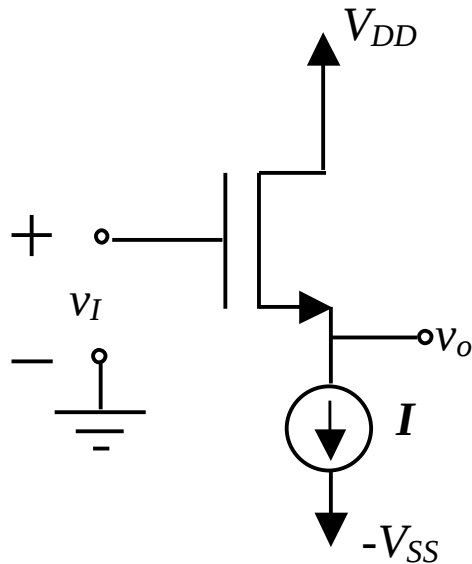
$$v_{o_{\min}} = 2 - 1 = 1V$$

$$V_A = 10 \times 10 = 100V \rightarrow r_o = \frac{100V}{100\mu A} = 1M\Omega$$

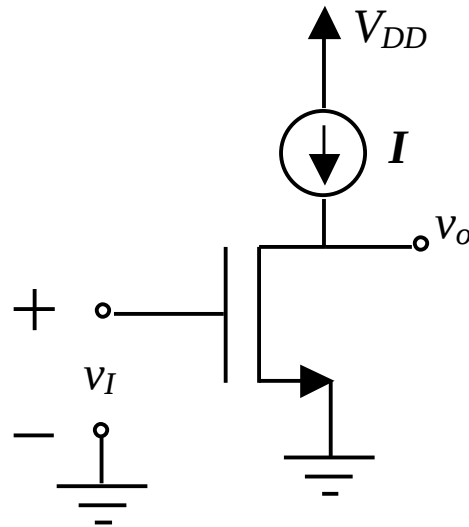
$$\Delta I_o = \frac{\Delta V_o}{r_o} = \frac{3V}{1M\Omega} = 3\mu A \Rightarrow +3\%$$

Basic MOSFET current mirror.

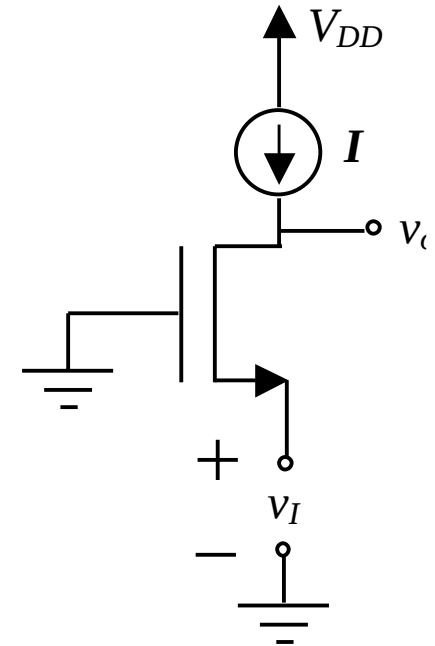
Basic amplifier configurations with current sources



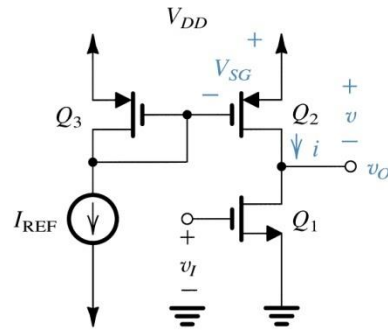
Source follower
or common-drain
amplifier



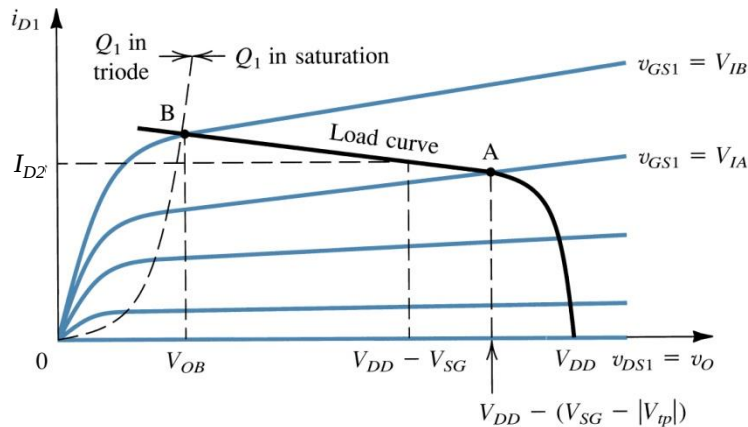
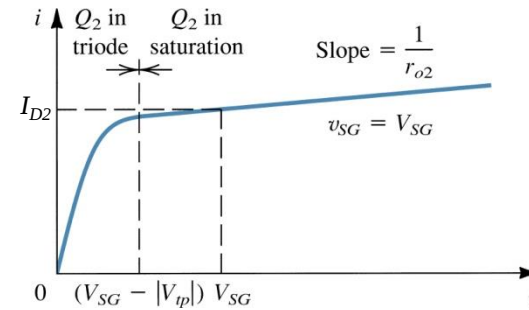
Common-source
amplifier



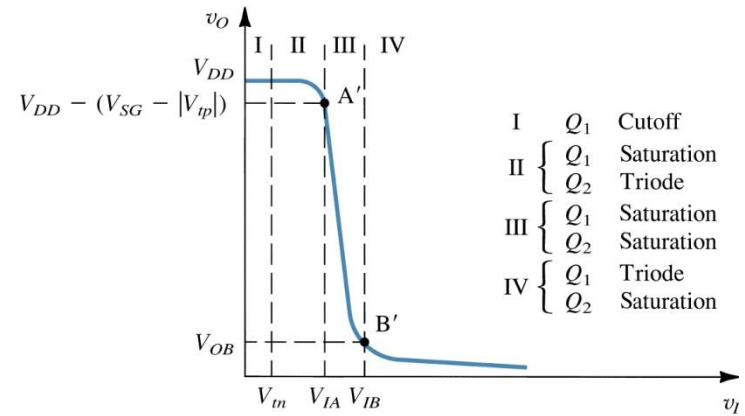
Common-gate
amplifier



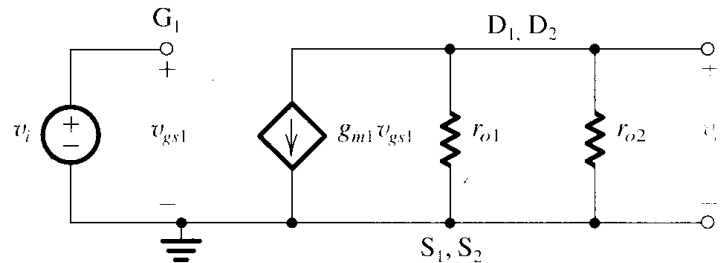
(a)



(c)



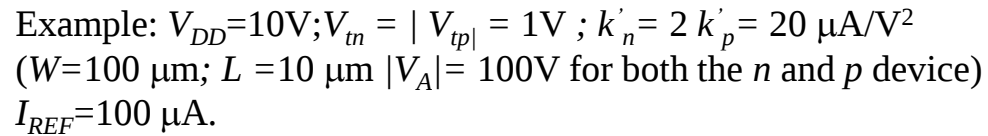
(d)



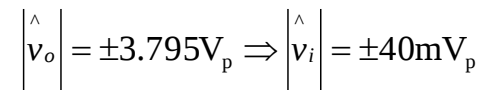
$$R_i = \infty \quad R_o = r_{o1} // r_{o2}$$

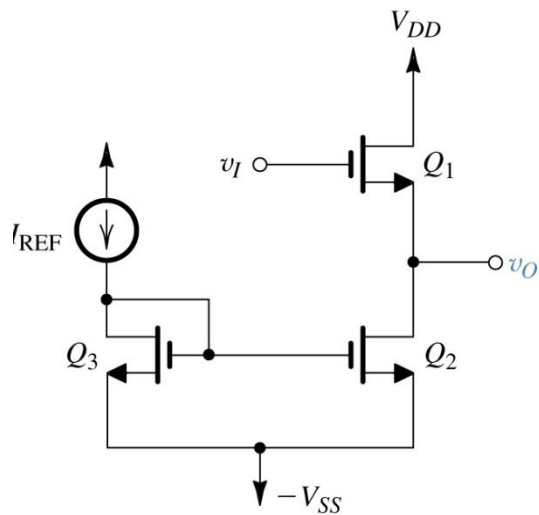
$$A_v = -g_{m1} (r_{o1} // r_{o2})$$

The CMOS common-source amplifier: **(a)** circuit; **(b)** i - v characteristic of the active-load Q_2 ; **(c)** graphical construction to determine the transfer characteristic; and transfer characteristic.

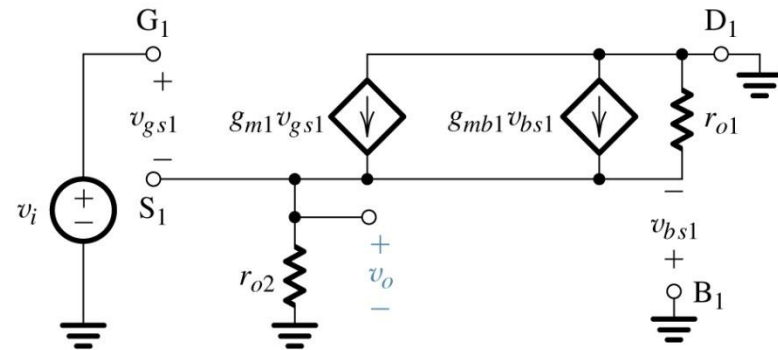


$$R_{in} = \infty \quad \therefore \quad R_o = (r_{o1} // r_{o2}) = 0.5\text{M}\Omega$$

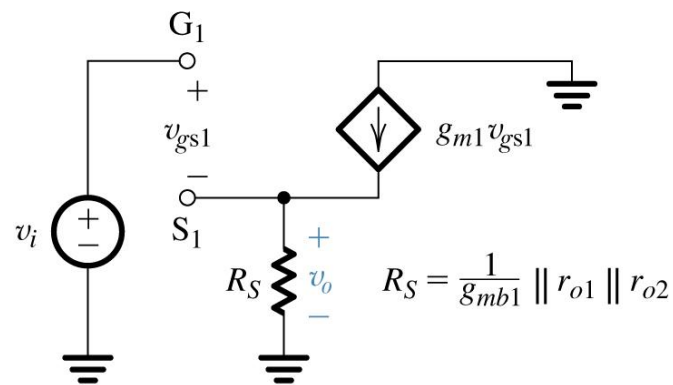




(a)



(b)



(c)

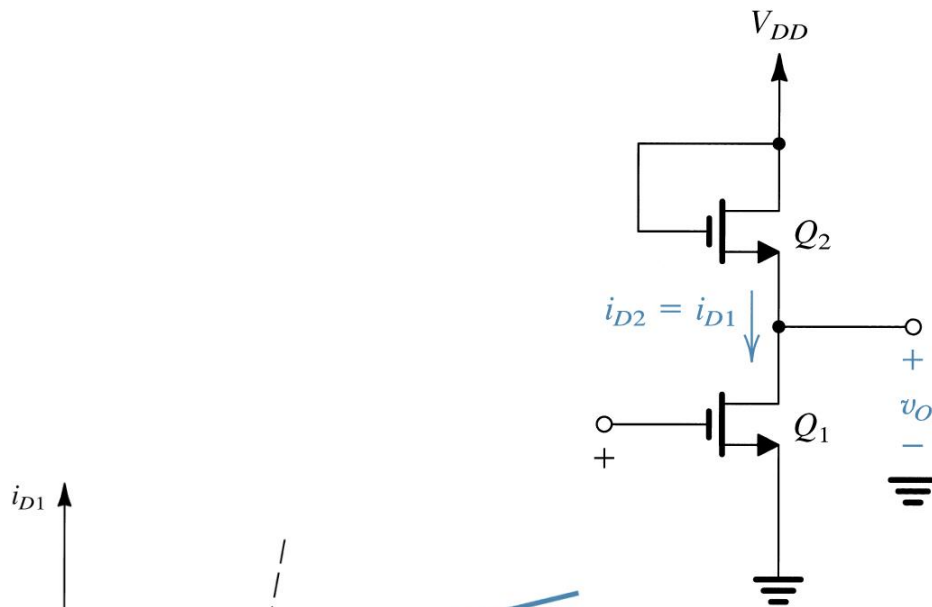
$$A_v \equiv \frac{v_o}{v_i} = \frac{g_{m1} R_S}{1 + g_{m1} R_S} = \frac{g_{m1}}{g_{m1} + g_{mb1} + \frac{1}{r_{o1}} + \frac{1}{r_{o2}}}$$

$$A_v \cong \frac{g_{m1}}{g_{m1} + g_{mb1}} = \frac{1}{1 + \chi}$$

$$R_o = \left(\frac{1}{g_{m1}} \right) \parallel \left(\frac{1}{g_{mb1}} \right) \parallel r_{o1} \parallel r_{o2}$$

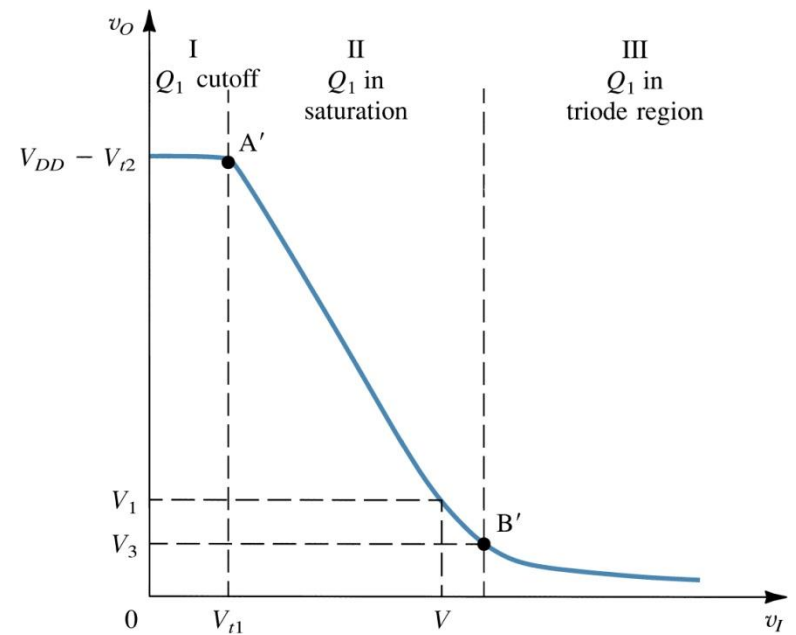
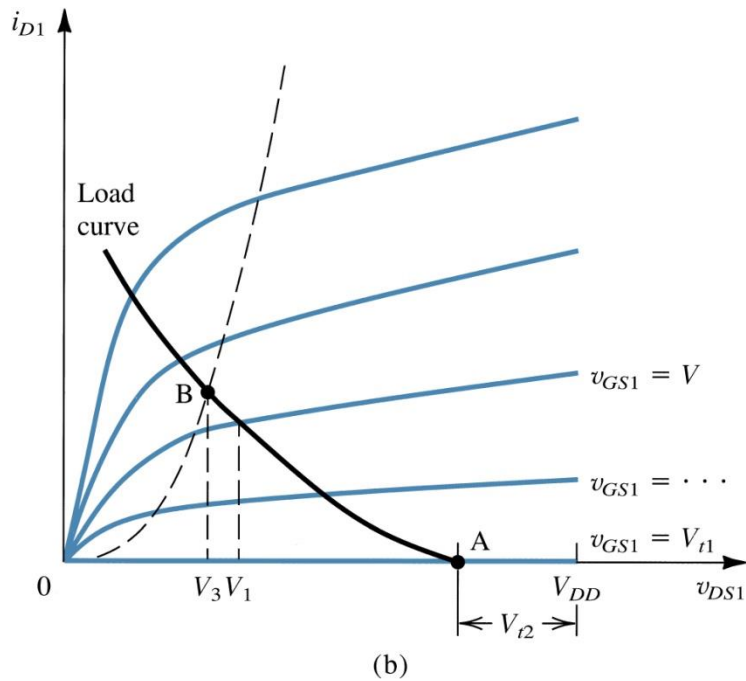
$$R_o \cong \left(\frac{1}{g_{m1}} \right) \parallel \left(\frac{1}{g_{mb1}} \right) = \frac{1}{g_{m1}(1 + \chi)}$$

The source follower: **(a)** circuit; **(b)** small-signal equivalent circuit; and **(c)** simplified version of the equivalent circuit.

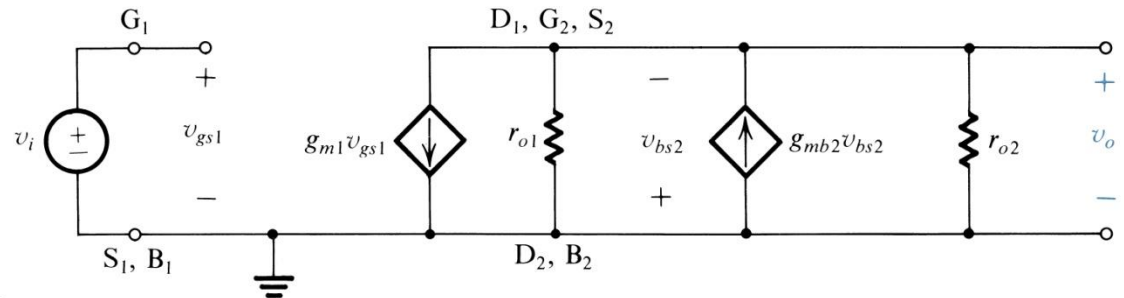
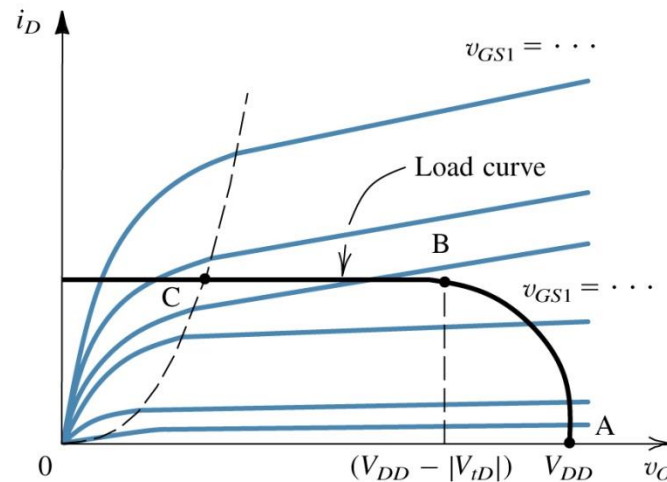
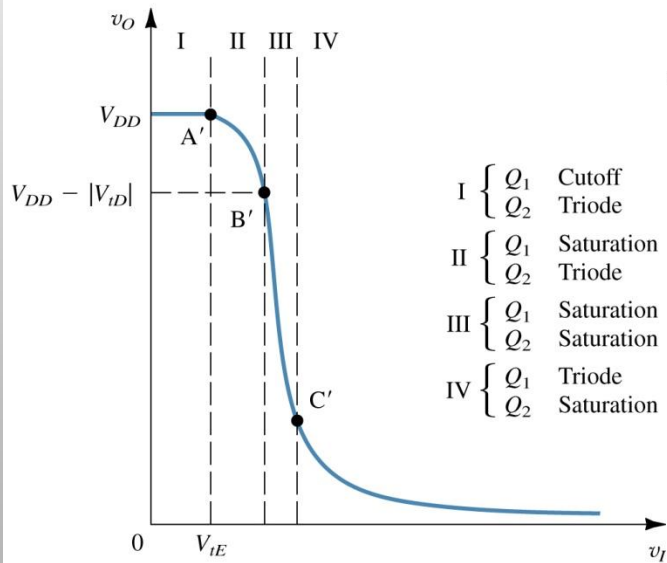
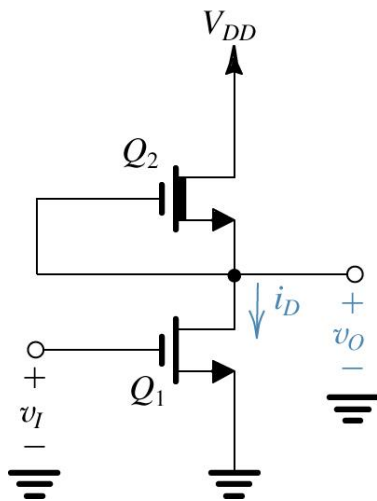


$$v_O = \left(V_{DD} - V_t + \sqrt{\frac{(W/L)_1}{(W/L)_2}} V_t \right) - \sqrt{\frac{(W/L)_1}{(W/L)_2}} v_I$$

$$A_v = -\sqrt{\frac{(W/L)_1}{(W/L)_2}} \frac{1}{1 + \chi_2} \cong -\sqrt{\frac{(W/L)_1}{(W/L)_2}}$$



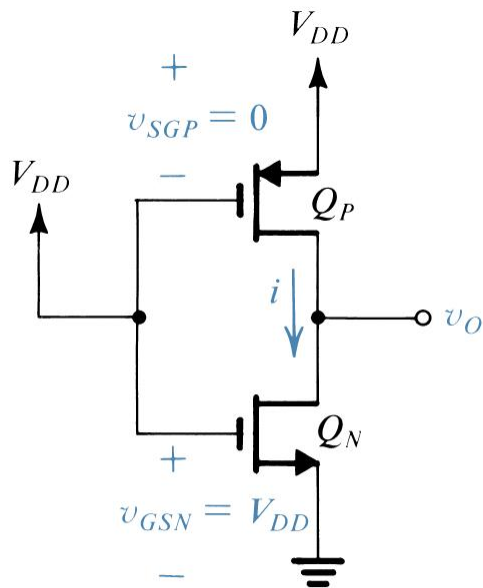
(a) NMOS amplifier with enhancement load; (b) graphical determination of the transfer characteristic; (c) transfer characteristic.



$$A_v \equiv \frac{v_o}{v_i} = -g_{m1} \left[\left(\frac{1}{g_{mb1}} \right) // r_{o1} // r_{o2} \right]$$

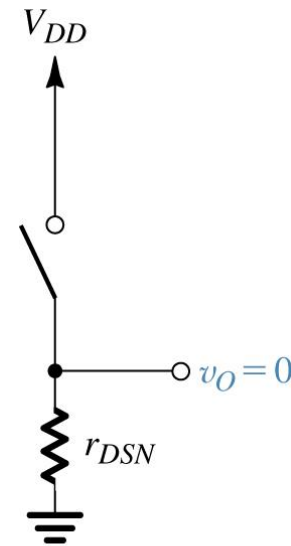
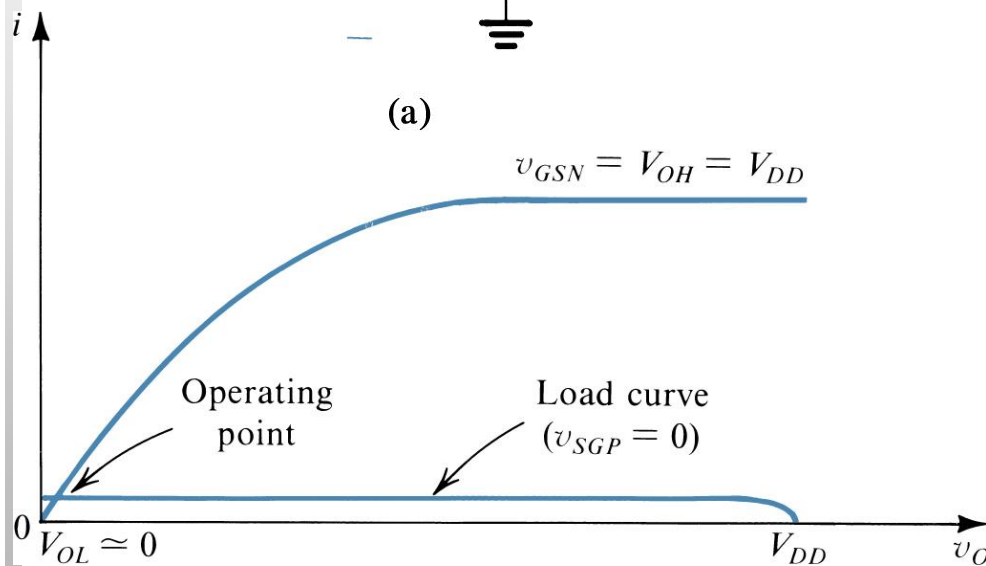
$$A_v \cong -\frac{g_{m1}}{g_{mb2}} = \sqrt{\frac{(W/L)_1}{(W/L)_2}} \frac{1}{\chi}$$

The NMOS amplifier with depletion load: **(a)** circuit; **(b)** graphical construction to determine the transfer characteristic; and **(c)** transfer characteristic.



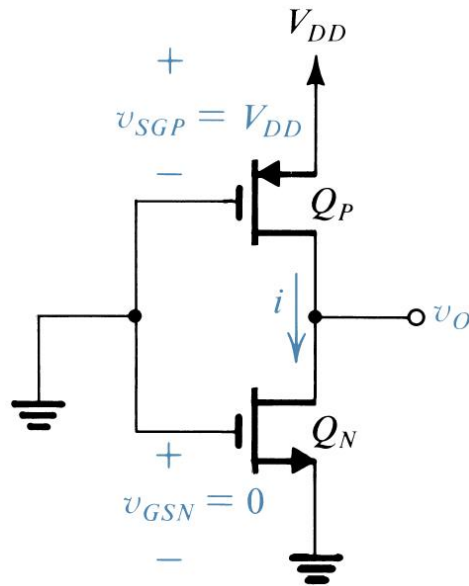
$$r_{DSN} = \frac{1}{\left[k'_n \left(\frac{W}{L} \right)_n (V_{DD} - V_{tn}) \right]}$$

(a)

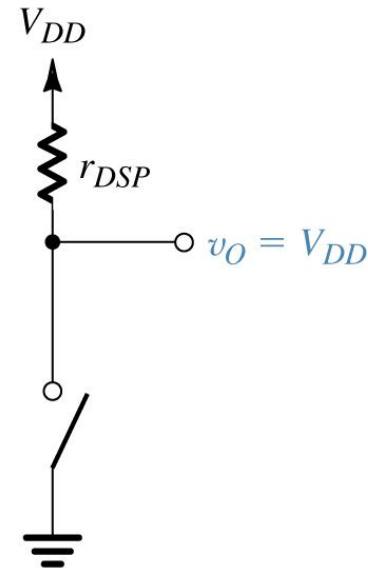
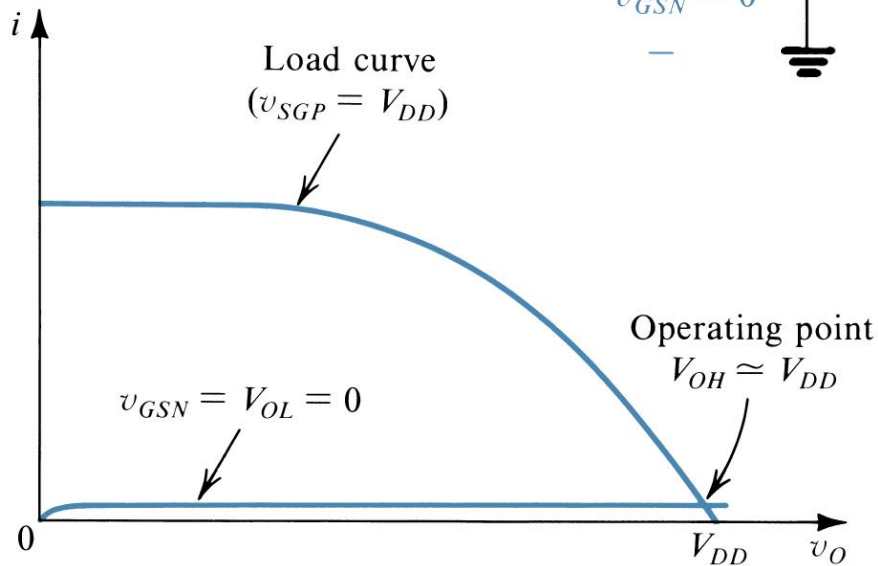


(c)

Operation of the CMOS inverter when v_1 is high: (a) circuit with $v_1 = V_{DD}$ (logic-1 level, or V_{OH}); (b) graphical construction to determine the operating point; and (c) equivalent circuit.

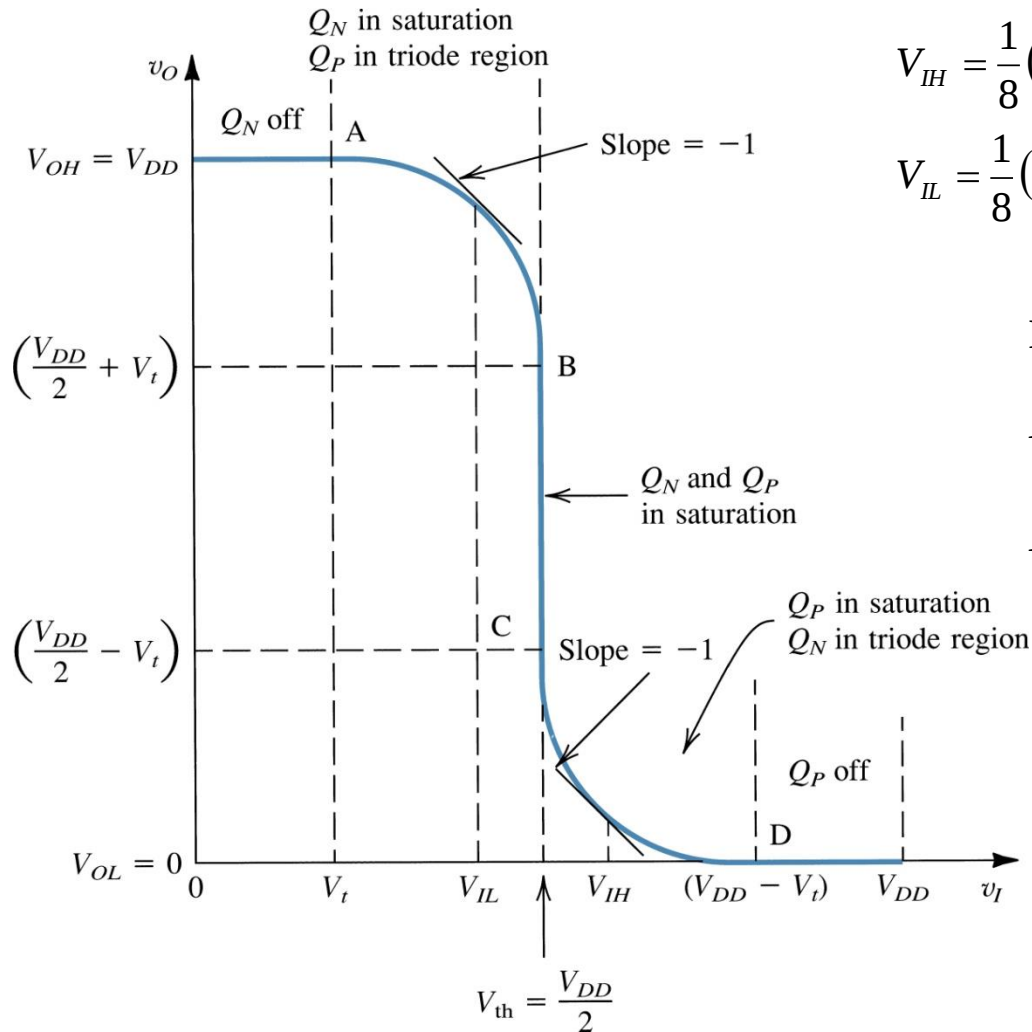


$$r_{DSP} = \frac{1}{\left[k'_p \left(\frac{W}{L} \right)_p (V_{DD} - |V_{tp}|) \right]}$$



(c)

Operation of the CMOS inverter when v_1 is low: (a) circuit with $v_1 = 0\text{V}$ (logic-0 level, or V_{OL}); (b) graphical construction to determine the operating point; and (c) equivalent circuit.



$$V_{IH} = \frac{1}{8}(5V_{DD} - 2V_t)$$

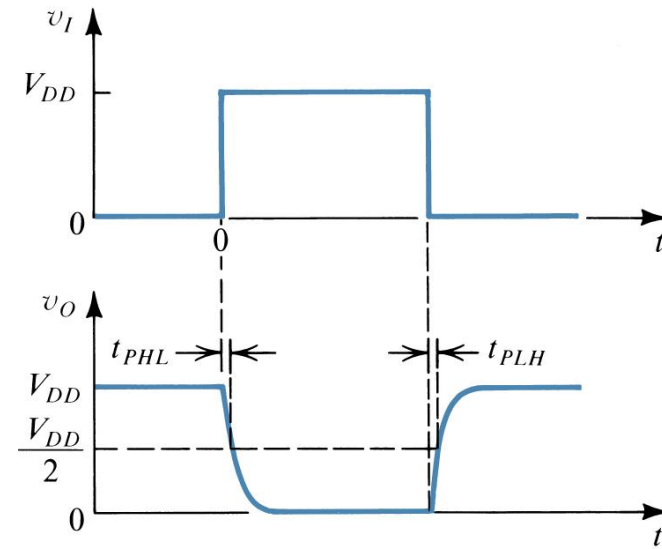
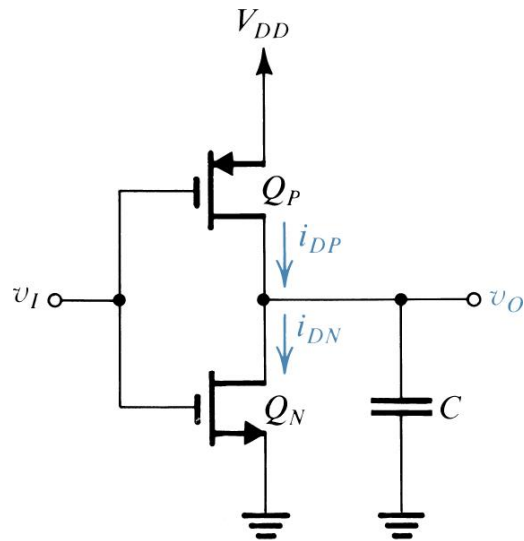
$$V_{IL} = \frac{1}{8}(3V_{DD} - 2V_t)$$

Noise Margins

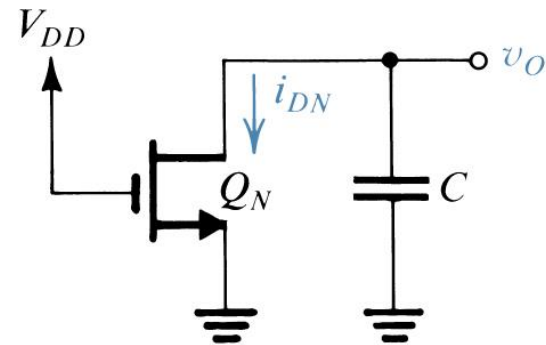
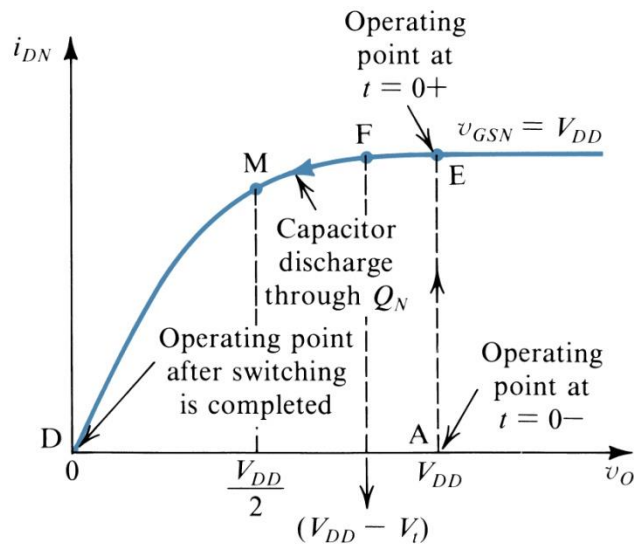
$$NM_H = \frac{1}{8}(3V_{DD} + 2V_t)$$

$$NM_L = \frac{1}{8}(3V_{DD} + 2V_t)$$

The voltage transfer characteristic of the CMOS inverter.

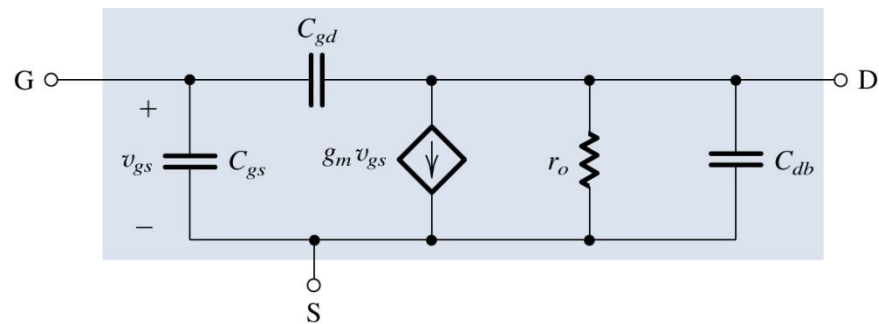
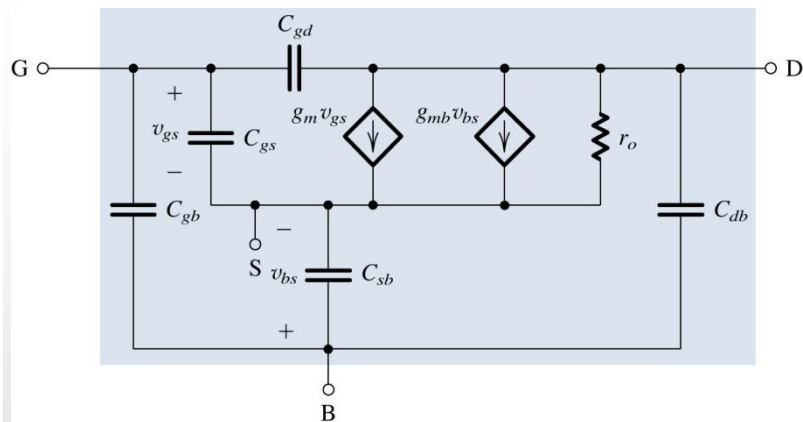


(b)

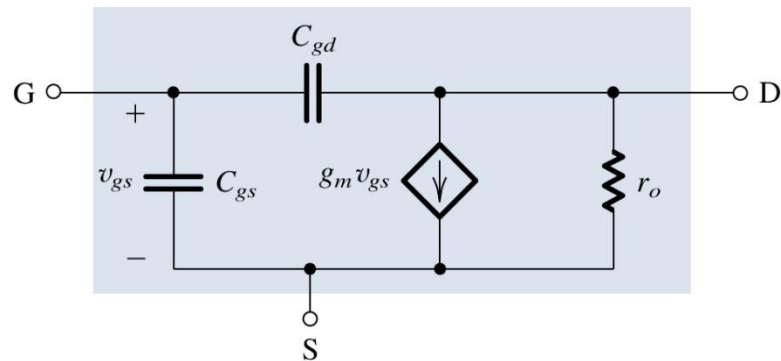


(d)

Dynamic operation of a capacitively loaded CMOS inverter: (a) circuit; (b) input and output waveforms; (c) trajectory of the operating point as the input goes high and C discharges through the Q_N ; (d) equivalent circuit during the capacitor discharge.



(b)



(c)

Strong inversion and saturation:

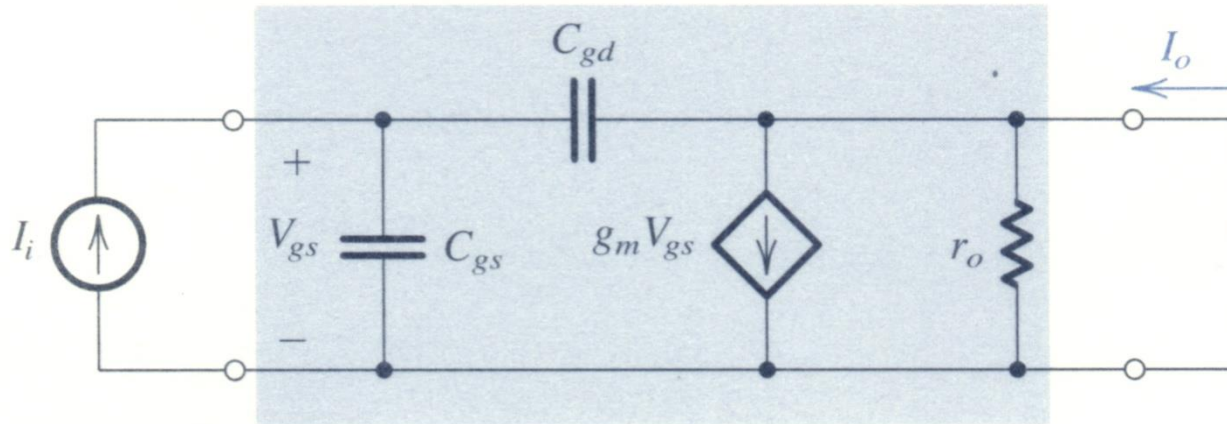
$$V_{GS} - V_t > 200 \text{ mV}$$

$$g_m = \sqrt{2 k (W/L) I_D}$$

$$r_o = \frac{V_A + V_{DS}}{I_D}$$

$$C_{gs} = \frac{2}{3} C_{ox} W L$$

(a) High-frequency equivalent circuit model for the MOSFET; (b) the equivalent circuit for the case the source is connected to the substrate (body); (c) the equivalent circuit model of (b) with C_{db} neglected (to simplify analysis).



$$\frac{I_o}{I_i} = \frac{g_m}{s(C_{gs} + C_{gd})}$$

For physical frequencies $s = j\omega$, it can be seen that the magnitude of the current gain becomes unity at the frequency:

$$f_T = \frac{g_m}{2\pi(C_{gs} + C_{gd})}$$

Determining the short-circuit current gain I_o/I_i .

When to use JFETs

- ✓ JFET have much higher input impedances and much lower input currents than BJTs.
- ✓ BJTs are more linear than JFETs.
- ✓ The gain of a BJT is much higher than that of a JFET.

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